

# 16-Bit, 12 GSPS, RF DAC and Digital Upconverter

### <span id="page-0-0"></span>**FEATURES**

**DAC update rate up to 12 GSPS (minimum) Direct RF synthesis at 6 GSPS (minimum) DC to 3 GHz in nonreturn-to-zero (NRZ) mode DC to 6 GHz in 2× NRZ mode 1.5 GHz to 7.5 GHz in Mix-Mode Selectable interpolation 6×, 8×, 12×, 16×, 24×** 

**Excellent dynamic performance**

#### <span id="page-0-1"></span>**APPLICATIONS**

**Broadband communications systems DOCSIS 3.1 cable modem termination system (CMTS)/ video on demand (VOD)/edge quadrature amplitude modulation (EQAM) Wireless communications infrastructure MC-GSM, W-CDMA, LTE, LTE-A, point to point**

#### <span id="page-0-2"></span>**GENERAL DESCRIPTION**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf)<sup>1</sup> is a high performance, 16-bit digital-to-analog converter (DAC) that supports data rates to 6 GSPS. The DAC core is based on a quad-switch architecture coupled with a 2× interpolator filter that enables an effective DAC update rate of up to 12 GSPS in some modes. The high dynamic range and bandwidth makes this DAC ideally suited for the most demanding high speed radio frequency (RF) DAC applications.

<span id="page-0-4"></span>Superior RF performance and deep interpolation rates enable use of th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) in many wireless infrastructure applications, including MC-GSM, W-CDMA, LTE, and LTE-A.

Data Sheet **[AD9163](http://www.analog.com/AD9163?doc=AD9163.pdf)** 

The wide bandwidth of up to 1 GHz and the complex NCO and digital upconverter enable dual band and triple band direct RF synthesis of wireless infrastructure signals, eliminating costly analog upconverters.

Wide analog bandwidth capability combines with high dynamic range to support DOCSIS 3.1 cable infrastructure compliance from the minimum of one carrier up to 1 GHz of signal bandwidth, making it ideal for cable multiple dwelling unit (MDU) applications. A 2× interpolator filter (FIR85) enables th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) to be configured for lower data rates and converter clocking to reduce the overall system power and ease the filtering requirements. In Mix-Mode™ operation, the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) can reconstruct RF carriers in the second and third Nyquist zones up to 7.5 GHz while still maintaining exceptional dynamic range. The output current can be programmed from 8 mA to 38.76 mA. Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) data interface consists of up to eight JESD204B serializer/deserializer (SERDES) lanes that are programmable in terms of lane speed and number of lanes to enable application flexibility.

A serial peripheral interface (SPI) configures th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) and monitors the status of all the registers. The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is offered in a 169-ball, 11 mm × 11 mm, 0.8 mm pitch CSP\_BGA package.

#### <span id="page-0-3"></span>**PRODUCT HIGHLIGHTS**

- 1. High dynamic range and signal reconstruction bandwidth supports RF signal synthesis of up to 7.5 GHz.
- 2. Up to eight lanes JESD204B SERDES interface, flexible in terms of number of lanes and lane speed.
- 3. Bandwidth and dynamic range to meet multiband wireless communications standards with margin.



<span id="page-0-5"></span><sup>1</sup> Protected by U.S. Patents 6,842,132 and 7,796,971.

#### **Rev. D [Document Feedback](https://form.analog.com/Form_Pages/feedback/documentfeedback.aspx?doc=AD9163.pdf&product=AD9163&rev=D)**

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# AD9163

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### <span id="page-2-0"></span>**REVISION HISTORY**



### **7/2017—Rev. B to Rev. C**





#### **2/2017—Rev. 0 to Rev. A**



**7/2016—Revision 0: Initial Version**

## <span id="page-3-0"></span>**SPECIFICATIONS DC SPECIFICATIONS**

<span id="page-3-1"></span>VDD25\_DAC = 2.5 V, VDD12A = VDD12\_CLK = 1.2 V, VNEG\_N1P2 = −1.2 V, DVDD = 1.2 V, IOVDD = 2.5 V, VDD\_1P2 = DVDD\_1P2 = PLL\_LDO\_VDD12 = 1.2 V, SYNC\_VDD\_3P3 = 3.3 V, DAC output full-scale current (I<sub>OUTFS</sub>) = 40 mA, and T<sub>A</sub> = −40°C to +85°C, unless otherwise noted.

<span id="page-3-2"></span>**Table 1.** 



<sup>1</sup> See the Clock Input section for more details.

<sup>2</sup> For the lowest noise performance, use a separate power supply filter network for the VDD12\_CLK and the VDD12A pins.

3 IOVDD can range from 1.8 V to 3.3 V, with ±5% tolerance.

 $^4$  The adjusted DAC update rate is calculated as f $_{\rm{pAC}}$  divided by the minimum required interpolation factor. For th[e AD9163,](http://www.analog.com/AD9163?doc=ad9163.pdf) the minimum interpolation factor is 6. Therefore, with  $f_{\text{DMC}} = 6$  GSPS,  $f_{\text{DMC}}$  adjusted = 1 GSPS. When FIR85 is enabled, which puts the device into 2× NRZ mode,  $f_{\text{DMC}} = 2 \times$  (DAC clock input frequency), and the minimum interpolation increases to 12x (interpolation value). Thus, for th[e AD9163,](http://www.analog.com/AD9163?doc=ad9163.pdf) with FIR85 enabled and DAC clock = 6 GSPS, f<sub>DAC</sub> = 12 GSPS, minimum interpolation = 12x, and the adjusted DAC update rate = 1 GSPS.

### <span id="page-4-0"></span>**DAC INPUT CLOCK OVERCLOCKING SPECIFICATIONS**

VDD25\_DAC = 2.5 V, VDD12A = VDD12\_CLK = 1.2 V, VNEG\_N1P2 = −1.2 V, DVDD = 1.2 V, IOVDD = 2.5 V, VDD\_1P2 = DVDD\_1P2 = PLL\_LDO\_VDD12 = 1.2 V, SYNC\_VDD\_3P3 = 3.3 V, I<sub>OUTFS</sub> = 40 mA,  $T_A = -40^{\circ}C$  to +85°C, unless otherwise noted.

Maximum guaranteed speed using the temperatures and voltages conditions as shown i[n Table 2,](#page-4-2) where VDDx is VDD12\_CLK, DVDD, VDD\_1P2, DVDD\_1P2, and PLL\_LDO\_VDD12. Any DAC clock speed over 5.1 GSPS requires a maximum junction temperature of 105°C to avoid damage to the device. See [Table 10](#page-9-5) for details on maximum junction temperature permitted for certain clock speeds.

<span id="page-4-2"></span>

<sup>1</sup> T<sub>JMAX</sub> is the maximum junction temperature.

#### <span id="page-4-1"></span>**POWER SUPPLY DC SPECIFICATIONS**

IOUTFS = 40 mA, T<sup>A</sup> = −40°C to +85°C, unless otherwise noted. FIR85 is the finite impulse response with 85 dB digital attenuation.

#### **Table 3.**





**Table 4.** 



### <span id="page-5-0"></span>**SERIAL PORT AND CMOS PIN SPECIFICATIONS**

VDD25\_DAC = 2.5 V, VDD12A = VDD12\_CLK = 1.2 V, VNEG\_N1P2 = −1.2 V, DVDD = 1.2 V, IOVDD = 2.5 V, VDD\_1P2 =  $DVDD_1P2 = PLL_LDO_VDD12 = 1.2 V, SYNC_VDD_3P3 = 3.3 V, I<sub>OUTFS</sub> = 40 mA, T<sub>A</sub> = -40°C to +85°C, unless otherwise noted.$ 



#### <span id="page-6-0"></span>**JESD204B SERIAL INTERFACE SPEED SPECIFICATIONS**

VDD25\_DAC = 2.5 V, VDD12A = VDD12\_CLK = 1.2 V, VNEG\_N1P2 = −1.2 V, DVDD = 1.2 V, IOVDD = 2.5 V, VDD\_1P2 = DVDD\_1P2 = PLL\_LDO\_VDD12 = 1.2 V, SYNC\_VDD\_3P3 = 3.3 V, I<sub>OUTFS</sub> = 40 mA,  $T_A = -40^{\circ}C$  to +85°C, unless otherwise noted.



#### <span id="page-6-1"></span>**SYSREF± TO DAC CLOCK TIMING SPECIFICATIONS**

VDD25\_DAC = 2.5 V, VDD12A = VDD12\_CLK = 1.2 V, VNEG\_N1P2 = −1.2 V, DVDD = 1.2 V, IOVDD = 2.5 V, VDD\_1P2 = DVDD\_1P2 = PLL\_LDO\_VDD12 = 1.2 V, SYNC\_VDD\_3P3 = 3.3 V, Iovres = 40 mA, T<sub>A</sub> = −40°C to +85°C, unless otherwise noted.

<span id="page-6-2"></span>

1 The SYSREF± pulse must be at least four DAC clock edges wide plus the setup and hold times i[n Table 6.](#page-6-2) For more information, see th[e Sync Processing Modes](#page-37-0)  [Overview](#page-37-0) section.



Figure 2. SYSREF± to DAC Clock Timing Diagram (Only SYSREF+ and CLK+ Shown)

#### <span id="page-7-0"></span>**DIGITAL INPUT DATA TIMING SPECIFICATIONS**

VDD25\_DAC = 2.5 V, VDD12A = VDD12\_CLK = 1.2 V, VNEG\_N1P2 = −1.2 V, DVDD = 1.2 V, IOVDD = 2.5 V, VDD\_1P2 = DVDD\_1P2 = PLL\_LDO\_VDD12 = 1.2 V, SYNC\_VDD\_3P3 = 3.3 V, I<sub>OUTFS</sub> = 40 mA,  $T_A = -40^{\circ}C$  to +85°C, unless otherwise noted.



<sup>1</sup> Total latency (or pipeline delay) through the device is calculated as follows:

Total Latency = Interface Latency + Fixed Latency + Variable Latency + Pipeline Delay Se[e Table 32](#page-49-3) for examples of the pipeline delay per block.

<sup>2</sup> PCLK is the internal processing clock for the  $AD9163$  and equals the lane rate  $\div$  40.

### <span id="page-7-1"></span>**JESD204B INTERFACE ELECTRICAL SPECIFICATIONS**

VDD25\_DAC = 2.5 V, VDD12A = VDD12\_CLK = 1.2 V, VNEG\_N1P2 = −1.2 V, DVDD = 1.2 V, IOVDD = 2.5 V, VDD\_1P2 = DVDD\_1P2 = PLL\_LDO\_VDD12 = 1.2 V, SYNC\_VDD\_3P3 = 3.3 V, I<sub>OUTFS</sub> = 40 mA,  $T_A = -40^{\circ}C$  to +85°C, unless otherwise noted. V<sub>TT</sub> is the termination voltage.

#### **Table 8.**



<sup>1</sup> As measured on the input side of the ac coupling capacitor.

2 IEEE Standard 1596.3 LVDS compatible.

#### <span id="page-8-0"></span>**AC SPECIFICATIONS**

VDD25\_DAC = 2.5 V, VDD12A = VDD12\_CLK = 1.2 V, VNEG\_N1P2 = −1.2 V, DVDD = 1.2 V, IOVDD = 2.5 V, VDD\_1P2 =  $DVDD_1P2 = PLL\_LDO_VDD12 = 1.2 V, SYNC_VDD_3P3 = 3.3 V, I<sub>OUTFS</sub> = 40 mA, T<sub>A</sub> = 25°C, unless otherwise noted.$ 



<sup>1</sup> See th[e Clock Input](#page-62-0) section for more details on optimizing SFDR and reducing the image of the fundamental with clock input tuning.

# <span id="page-9-0"></span>ABSOLUTE MAXIMUM RATINGS

#### <span id="page-9-5"></span>**Table 10.**



<sup>1</sup> Some operating modes of the device may cause the device to approach or exceed the maximum junction temperature during operation at supported ambient temperatures. Removal of heat from the device may require additional measures such as active airflow, heat sinks, or other measures.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

#### <span id="page-9-1"></span>**REFLOW PROFILE**

The [AD9163](http://analog.com/AD9163?doc=AD9163.pdf) reflow profile is in accordance with the JEDEC JESD204B criteria for Pb-free devices. The maximum reflow temperature is 260°C.

#### <span id="page-9-2"></span>**THERMAL MANAGEMENT**

The [AD9163](http://analog.com/AD9163?doc=AD9163.pdf) is a high power device that can dissipate nearly 3 W depending on the user application and configuration. Because of the power dissipation, the [AD9163](http://analog.com/AD9163?doc=AD9163.pdf) uses an exposed die package to give the customer the most effective method of controlling the die temperature. The exposed die allows cooling of the die directly.

[Figure 3](#page-9-6) shows the profile view of the device mounted to a user printed circuit board (PCB) and a heat sink (typically the aluminum case) to keep the junction (exposed die) below the maximum junction temperature in [Table 10.](#page-9-5) 



#### <span id="page-9-6"></span><span id="page-9-3"></span>**THERMAL RESISTANCE**

Typical  $\theta_{JA}$  and  $\theta_{JC}$  values are specified for a 4-layer JEDEC 2S2P high effective thermal conductivity test board for balled surface-mount packages.  $\theta_{JA}$  is obtained in still air conditions (JESD51-2). Airflow increases heat dissipation, effectively reducing θ<sub>JA</sub>.  $θ$ <sub>JC</sub> is obtained with the test case temperature monitored at the bottom of the package.

$$
\theta_{JA} = \frac{T_f - T_A}{P}
$$

$$
\theta_{JC} = \frac{T_f - T_C}{P}
$$

where:

 $\theta_{JA}$  is the natural convection junction-to-ambient air thermal resistance measured in a one-cubic foot sealed enclosure.  $T_I$  is the die junction temperature.

 $T_A$  is the ambient temperature in a still air environment.

P is the total power (heat) dissipated in the chip.

 $\theta$ <sub>IC</sub> is the junction-to-case thermal resistance. (In the case of the [AD9163,](http://analog.com/AD9163?doc=AD9163.pdf) this is measured at the top of the package on the bare die.)

 $T_c$  is the package case temperature. (In the case of the AD9163, the temperature is measured on the bare die.)

#### **Table 11. Thermal Resistance**



#### <span id="page-9-4"></span>**ESD CAUTION**



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

# <span id="page-10-0"></span>PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

	$\mathbf{1}$	$\mathbf 2$	3	4	5	6	$\overline{7}$	8	9	10	11	12	13	
А	<b>VSS</b>	VNEG_N1P2	VDD25_DAC	VNEG_N1P2	VDD25_DAC	OUTPUT-	OUTPUT+	VDD25_DAC	VNEG_N1P2	VDD25_DAC	<b>VSS</b>	<b>ISET</b>	<b>VREF</b>	A
в	$CLK+$	<b>VSS</b>	<b>VSS</b>	VDD25_DAC	VNEG_N1P2	VDD25_DAC	VDD25_DAC	VNEG_N1P2	VDD25_DAC	<b>VDD12A</b>	<b>VDD12A</b>	<b>VDD25_DAC</b>	VNEG_N1P2	в
с	CLK-	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	VDD25_DAC	VNEG_N1P2	VNEG_N1P2	VDD25_DAC	<b>VBG_NEG</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	C
D	<b>VSS</b>	VDD12_CLK	VDD12_CLK	VDD12_CLK	VDD12_CLK	<b>VSS</b>	<b>VSS</b>	VDD12_CLK	VDD12_CLK	VDD12_CLK	VDD12_CLK	VDD12_CLK	VDD12_CLK	D
E	VDD12_CLK	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>DVDD</b>	<b>DVDD</b>	<b>VSS</b>	<b>DVDD</b>	<b>DVDD</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	Е
F	SYSREF+	<b>SYSREF-</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	$\overline{\text{cs}}$	<b>VSS</b>	F
G	<b>VSS</b>	<b>VSS</b>	TX_ENABLE	<b>IRQ</b>	<b>DVDD</b>	<b>DVDD</b>	<b>DVDD</b>	<b>DVDD</b>	<b>DVDD</b>	<b>SDIO</b>	<b>SDO</b>	<b>VSS</b>	<b>VSS</b>	G
н	SERDIN7+	SERDIN7-	<b>VDD_1P2</b>	<b>RESET</b>	<b>IOVDD</b>	<b>DVDD_1P2</b>	<b>VSS</b>	<b>DVDD_1P2</b>	<b>IOVDD</b>	<b>SCLK</b>	<b>VDD_1P2</b>	SERDINO-	SERDINO+	н
J	<b>VSS</b>	<b>VSS</b>	<b>VDD_1P2</b>	<b>DNC</b>	<b>DNC</b>	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	SYNCOUT-	SYNCOUT+	<b>VDD_1P2</b>	<b>VSS</b>	<b>VSS</b>	J
к	SERDIN6+	SERDING-	<b>VTT_1P2</b>	<b>SYNC</b> <b>VDD_3P3</b>	<b>DNC</b>	<b>VSS</b>	PLL CLK <b>VDD12</b>	PLL LDO <b>VDD12</b>	<b>DNC</b>	<b>SYNC</b> <b>VDD_3P3</b>	<b>VTT_1P2</b>	SERDIN1-	SERDIN1+	Κ
г	<b>VSS</b>	<b>VSS</b>	<b>VDD_1P2</b>	<b>VDD_1P2</b>	<b>VDD_1P2</b>	<b>VSS</b>	<b>DNC</b>	<b>VSS</b>	<b>VDD_1P2</b>	<b>VDD_1P2</b>	<b>VDD_1P2</b>	<b>VSS</b>	<b>VSS</b>	г
м	<b>VSS</b>	<b>VSS</b>	SERDIN5+	<b>VSS</b>	SERDIN4+	<b>VSS</b>	PLL_LDO <b>BYPASS</b>	<b>VSS</b>	SERDIN3+	<b>VSS</b>	SERDIN2+	<b>VSS</b>	<b>VSS</b>	M
	N BIAS VDD 1P2	<b>VSS</b>	<b>SERDIN5-</b>	<b>VSS</b>	SERDIN4-	<b>VSS</b>	<b>VSS</b>	<b>VSS</b>	<b>SERDIN3-</b>	<b>VSS</b>	SERDIN2-	<b>VSS</b>	<b>BIAS</b> <b>VDD_1P2</b>	N
	$\mathbf{1}$	$\overline{2}$	3	$\bf{4}$	5	6	$\overline{7}$	8	9	10	11	12	13	
	<b>GROUND</b>	-1.2V ANALOG SUPPLY <b>2.5V ANALOG SUPPLY</b> <b>1.2V DAC SUPPLY</b>		<b>1.2V DAC CLK SUPPLY</b> <b>SERDES INPUT</b> SERDES 3.3V VCO SUPPLY SERDES 1.2V SUPPLY				<b>DAC RF SIGNALS</b> <b>REFERENCE</b> SYSREF±/SYNCOUT± CMOS I/O <b>IOVDD</b>						
$DNC = DO NOT CONNECT$ .														

Figure 4. 169-Ball CSP\_BGA Pin Configuration







# <span id="page-12-0"></span>TYPICAL PERFORMANCE CHARACTERISTICS

### <span id="page-12-1"></span>**STATIC LINEARITY**

 $I<sub>OUTFS</sub> = 40 mA$ , nominal supplies,  $T_A = 25°C$ , unless otherwise noted.





#### <span id="page-13-0"></span>**AC PERFORMANCE (NRZ MODE)**

 $I<sub>OUTFS</sub> = 40$  mA,  $f<sub>DAC</sub> = 5.0$  GSPS, nominal supplies,  $T_A = 25$ °C, unless otherwise noted.



Figure 12. Single-Tone Spectrum at  $f_{\text{OUT}} = 70$  MHz (FIR85 Enabled)



Figure 13. SFDR vs.  $f_{OUT}$  over  $f_{DAC}$ 



Figure 14. Single-Tone Spectrum at  $f_{\text{OUT}} = 2000$  MHz



Figure 15. Single-Tone Spectrum at  $f_{OUT} = 2000$  MHz (FIR85 Enabled)



Figure 16. IMD vs. fout over f<sub>DAC</sub>

 $I<sub>OUTFS</sub> = 40 mA$ ,  $f<sub>DAC</sub> = 5.0 GSPS$ , nominal supplies,  $T_A = 25°C$ , unless otherwise noted.



Figure 17. SFDR vs. fout over Digital Scale



Figure 18. SFDR for In-Band Second Harmonic vs.  $f_{\text{OUT}}$  over Digital Scale



Figure 19. SFDR for In-Band Third Harmonic vs.  $f_{OUT}$  over Digital Scale









IOUTFS = 40 mA,  $f_{\text{DAC}} = 5.0$  GSPS, nominal supplies,  $T_A = 25^{\circ}C$ , unless otherwise noted.



Figure 23. SFDR vs. fout over Temperature



Figure 24. Single-Tone NSD Measured at 70 MHz vs. fout over fDAC



Figure 25. Single-Tone NSD Measured at 10% Offset from  $f_{\text{OUT}}$  vs.  $f_{\text{OUT}}$  over  $f_{\text{DAC}}$ 



Figure 26. W-CDMA NSD Measured at 70 MHz vs.  $f_{OUT}$  over  $f_{DAC}$ 



Figure 27. W-CDMA NSD Measured at 10% Offset from fout vs. fout over foac



Figure 28. IMD vs.  $f_{OUT}$  over Temperature

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IOUTFS = 40 mA,  $f_{DAC} = 5.0$  GSPS, nominal supplies,  $T_A = 25$ °C, unless otherwise noted.



Figure 29. Single-Tone NSD Measured at 70 MHz vs.  $f_{\text{OUT}}$  over Temperature



Figure 30. Single-Tone NSD Measured at 10% Offset from  $f_{\text{OUT}}$  vs.  $f_{\text{OUT}}$  over **Temperature** 



Figure 31. Single-Carrier W-CDMA at 877.5 MHz



Figure 32. W-CDMA NSD Measured at 70 MHz vs. four over Temperature



Figure 33. W-CDMA NSD Measured at 10% Offset from fout vs. fout over **Temperature** 



Figure 34. Two-Carrier W-CDMA at 875 MHz

14415-032

IOUTFS = 40 mA,  $f_{\text{DAC}} = 5.0$  GSPS, nominal supplies,  $T_A = 25^{\circ}C$ , unless otherwise noted.



Figure 35. Single-Carrier, W-CDMA Adjacent Channel Leakage Ratio (ACLR) vs.  $f_{OUT}$  (First ACLR, Second ACLR)



Figure 36. Single-Carrier, W-CDMA ACLR vs. four (Third ACLR, Fourth ACLR, Fifth ACLR)



Figure 37. SSB Phase Noise vs. Offset over  $f_{\text{OUT}}$ ,  $f_{\text{DAC}} = 4000 \text{ MSPS}$ (Two Different DAC Clock Sources Used for Best Composite Curve)



Figure 38. Two-Carrier, W-CDMA ACLR vs.  $f_{OUT}$  (First ACLR, Second ACLR)



Figure 39. Two-Carrier, W-CDMA ACLR vs. fout (Third ACLR, Fourth ACLR, Fifth ACLR)



Figure 40. SSB Phase Noise vs. Offset over  $f_{\text{OUT}}$ ,  $f_{\text{DAC}} = 6000 \text{ MSPS}$ 

### <span id="page-18-0"></span>**AC (MIX-MODE)**

 $I<sub>OUTFS</sub> = 40$  mA,  $f<sub>DAC</sub> = 5.0$  GSPS, nominal supplies,  $T_A = 25$ °C, unless otherwise noted.



Figure 42. Single-Tone Spectrum at  $f_{\text{OUT}} = 2350$  MHz (FIR85 Enabled)



Figure 43. Single-Tone NSD vs.  $f_{OUT}$ 



Figure 44. Single-Tone Spectrum at  $f_{OUT} = 4000$  MHz



Figure 45. Single-Tone Spectrum at  $f_{\text{OUT}} = 4000$  MHz (FIR85 Enabled)



Figure 46. W-CDMA NSD vs.  $f_{OUT}$ 

IOUTFS = 40 mA,  $f_{\text{DAC}} = 5.0$  GSPS, nominal supplies,  $T_A = 25^{\circ}C$ , unless otherwise noted.



Figure 47. SFDR vs. fout over Digital Scale









**fOUT (MHz)** Figure 52. IMD vs. fout over f<sub>DAC</sub>

**40001000 2000 3000 5000 6000 900080007000**

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IOUTFS = 40 mA,  $f_{DAC} = 5.0$  GSPS, nominal supplies,  $T_A = 25$ °C, unless otherwise noted.



Figure 53. Single-Carrier W-CDMA at 1887.5 MHz



Figure 54. Single-Carrier, W-CDMA ACLR vs. fout (First ACLR, Second ACLR)



Figure 55. Single-Carrier, W-CDMA ACLR vs. four (Third ACLR, Fourth ACLR, Fifth ACLR)



Figure 56. Four-Carrier W-CDMA at 1980 MHz



Figure 57. Four-Carrier, W-CDMA ACLR vs. four (First ACLR, Second ACLR)



Figure 58. Four-Carrier, W-CDMA ACLR vs. four (Third ACLR, Fourth ACLR, Fifth ACLR)

### <span id="page-21-0"></span>**DOCSIS PERFORMANCE (NRZ MODE)**

IOUTFS = 40 mA,  $f_{\text{DAC}}$  = 3.076 GSPS, nominal supplies, FIR85 enabled,  $T_A$  = 25°C, unless otherwise noted.



# Data Sheet **AD9163**

IOUTFS = 40 mA,  $f_{\text{DAC}}$  = 3.076 GSPS, nominal supplies, FIR85 enabled,  $T_A$  = 25°C, unless otherwise noted.



Figure 70. Eight Carriers at 950 MHz Output (Shuffle On)

IOUTFS = 40 mA, fDAC = 3.076 GSPS, nominal supplies, FIR85 enabled,  $T_A = 25^{\circ}$ C, unless otherwise noted.



Figure 71. In-Band Second Harmonic vs. four Performance for One DOCSIS Carrier



Figure 72. In-Band Second Harmonic vs.  $f_{\text{OUT}}$  Performance for Four DOCSIS Carriers



Figure 73. In-Band Second Harmonic vs. four Performance for Eight DOCSIS Carriers



Figure 74. In-Band Third Harmonic vs.  $f_{\text{OUT}}$  Performance for One DOCSIS Carrier



Figure 75. In-Band Third Harmonic vs.  $f_{\text{OUT}}$  Performance for Four DOCSIS Carriers



Figure 76. In-Band Third Harmonic vs.  $f_{\text{OUT}}$  Performance for Eight DOCSIS Carriers

IOUTFS = 40 mA,  $f_{\text{DAC}}$  = 3.076 GSPS, nominal supplies, FIR85 enabled,  $T_A$  = 25°C, unless otherwise noted.



Figure 77. Single-Carrier Adjacent Channel Power Ratio (ACPR) vs.  $f_{OUT}$ 







Figure 79. Eight-Carrier ACPR vs. fout



Figure 80. 16-Carrier ACPR vs.  $f_{OUT}$ 





Figure 82. 194-Carrier, Sinc Enabled, FIR85 Enabled

 $\rm I_{\rm OUTFS}$  = 40 mA,  $\rm f_{\rm DAC}$  = 3.076 GSPS, nominal supplies, FIR85 enabled, T<sub>A</sub> = 25°C, unless otherwise noted.



Figure 83. Gap Channel ACLR at 77 MHz



Figure 84. ACLR in Gap Channel vs.  $f_{GAP}$ 

# <span id="page-26-0"></span>**TERMINOLOGY**

#### **Integral Nonlinearity (INL)**

INL is the maximum deviation of the actual analog output from the ideal output, determined by a straight line drawn from zero scale to full scale.

#### **Differential Nonlinearity (DNL)**

DNL is the measure of the variation in analog value, normalized to full scale, associated with a 1 LSB change in digital input code.

#### **Offset Error**

Offset error is the deviation of the output current from the ideal of 0 mA. For OUTPUT+, 0 mA output is expected when all inputs are set to 0. For OUTPUT−, 0 mA output is expected when all inputs are set to 1.

#### **Gain Error**

Gain error is the difference between the actual and ideal output span. The actual span is determined by the difference between the output when the input is at its minimum code and the output when the input is at its maximum code.

#### **Temperature Drift**

Temperature drift is specified as the maximum change from the ambient (25°C) value to the value at either  $T_{MN}$  or  $T_{MAX}$ . For offset and gain drift, the drift is reported in ppm of full-scale range (FSR) per degree Celsius. For reference drift, the drift is reported in ppm per degree Celsius.

#### **Settling Time**

Settling time is the time required for the output to reach and remain within a specified error band around its final value, measured from the start of the output transition.

#### **Spurious-Free Dynamic Range (SFDR)**

SFDR is the difference, in decibels, between the peak amplitude of the output signal and the peak spurious signal within the dc to Nyquist frequency of the DAC. Typically, energy in this band is rejected by the interpolation filters. This specification,

therefore, defines how well the interpolation filters work and the effect of other parasitic coupling paths on the DAC output.

#### **Signal-to-Noise Ratio (SNR)**

SNR is the ratio of the rms value of the measured output signal to the rms sum of all other spectral components below the Nyquist frequency, excluding the first six harmonics and dc. The value for SNR is expressed in decibels.

#### **Interpolation Filter**

If the digital inputs to the DAC are sampled at a multiple rate of the interpolation rate ( $f<sub>DATA</sub>$ ), a digital filter can be constructed that has a sharp transition band near f<sub>DATA</sub>/2. Images that typically appear around the output data rate  $(f_{\text{DAC}})$  can be greatly suppressed.

#### **Adjacent Channel Leakage Ratio (ACLR)**

ACLR is the ratio in decibels relative to the carrier (dBc) between the measured power within a channel relative to its adjacent channel.

#### **Adjusted DAC Update Rate**

The adjusted DAC update rate is the DAC update rate divided by the smallest interpolating factor. For clarity on DACs with multiple interpolating factors, the adjusted DAC update rate for each interpolating factor may be given.

#### **Physical Lane**

Physical Lane x refers to SERDINx±.

#### **Logical Lane**

Logical Lane x refers to physical lanes after optionally being remapped by the crossbar block (Register 0x308 to Register 0x30B).

#### **Link Lane**

Link Lane x refers to logical lanes considered in the link.

# <span id="page-27-0"></span>THEORY OF OPERATION

Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is a 16-bit single RF DAC and digital upconverter with a SERDES interface[. Figure 1 s](#page-0-5)hows a detailed functional block diagram of th[e AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf) Eight high speed serial lanes carry data at a maximum speed of 12.5 Gbps, and either a 5 GSPS real input or a 2.5 GSPS complex input data rate to the DAC. Compared to either LVDS or CMOS interfaces, the SERDES interface simplifies pin count, board layout, and input clock requirements to the device.

The clock for the input data is derived from the DAC clock, or device clock (required by the JESD204B specification). This device clock is sourced with a high fidelity direct external DAC sampling clock. The performance of the DAC can be optimized by using on-chip adjustments to the clock input, accessible through the SPI port. The device can be configured to operate in one-lane, two-lane, three-lane, four-lane, six-lane, or eight-lane modes, depending on the required input data rate.

The digital datapath of th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) offers several interpolation modes (6×, 8×, 12×, 16×, and 24×) through either an initial half-band  $(2\times)$  or third-band  $(3\times)$  filter with programmable 80% or 90% bandwidth, and three subsequent half-band filters (all 90%) with a maximum DAC sample rate of 6 GSPS. An inverse sinc filter is provided to compensate for sinc related rolloff. An additional half-band filter, FIR85, takes advantage of the quad-switch architecture to interpolate on the falling edge of the clock, and effectively double the DAC update rate in 2× NRZ mode. A 48-bit programmable modulus NCO is provided to enable digital frequency shifts of signals with near infinite precision. The NCO can be operated with digital data from the SERDES interface and digital datapath. The 100 MHz speed of the SPI write interface enables rapid updating of the frequency tuning word of the NCO.

Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) DAC core provides a fully differential current output with a nominal full-scale current of 38.76 mA. The full-scale output current, I<sub>OUTFS</sub>, is user adjustable from 8 mA to 38.76 mA, typically. The differential current outputs are complementary. The DAC uses the patented quad-switch architecture, which enables DAC decoder options to extend the output frequency range into the second and third Nyquist zones with Mix-Mode, return to zero (RZ) mode, and 2× NRZ mode (with FIR85 enabled). Mix-Mode can be used to access 1.5 GHz to around 7.5 GHz. In the interpolation modes, the output can range from 0 Hz to 6 GHz in 2× NRZ mode using the NCO to shift a signal of up to 1.8 GHz instantaneous bandwidth to the desired four.

Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is capable of multichip synchronization that can both synchronize multiple DACs and establish a constant and deterministic latency (latency locking) path for the DACs. The latency for each of the DACs remains constant to within several DAC clock cycles from link establishment to link establishment. An external alignment (SYSREF±) signal makes th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) Subclass 1 compliant. Several modes of SYSREF± signal handling are available for use in the system.

An SPI configures the various functional blocks and monitors their statuses. The various functional blocks and the data interface must be set up in a specific sequence for proper operation (see th[e Start-Up Sequence s](#page-66-0)ection). Simple SPI initialization routines set up the JESD204B link and are included in the evaluation board package. This data sheet describes the various blocks of th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) in greater detail. Descriptions of the JESD204B interface, control parameters, and various registers to set up and monitor the device are provided. The recommended start-up routine reliably sets up the data link.

# <span id="page-28-0"></span>SERIAL PORT OPERATION

The serial port is a flexible, synchronous serial communications port that allows easy interfacing with many industry-standard microcontrollers and microprocessors. The serial input/output (I/O) is compatible with most synchronous transfer formats, including both the Motorola SPI and Intel® SSR protocols. The interface allows read/write access to all registers that configure th[e AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf) MSB first or LSB first transfer formats are supported. The serial port interface can be configured as a 4-wire interface or a 3-wire interface in which the input and output share a singlepin I/O (SDIO).



Figure 85. Serial Port Interface Pins

There are two phases to a communication cycle with the [AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf)  Phase 1 is the instruction cycle (the writing of an instruction byte into the device), coincident with the first 16 SCLK rising edges. The instruction word provides the serial port controller with information regarding the data transfer cycle, Phase 2 of the communication cycle. The Phase 1 instruction word defines whether the upcoming data transfer is a read or write, along with the starting register address for the following data transfer.

A logic high on the  $\overline{\text{CS}}$  pin followed by a logic low resets the serial port timing to the initial state of the instruction cycle. From this state, the next 16 rising SCLK edges represent the instruction bits of the current I/O operation.

The remaining SCLK edges are for Phase 2 of the communication cycle. Phase 2 is the actual data transfer between the device and the system controller. Phase 2 of the communication cycle is a transfer of one or more data bytes. Eight  $\times$  N SCLK cycles are needed to transfer N bytes during the transfer cycle. Registers change immediately upon writing to the last bit of each transfer byte, except for the frequency tuning word (FTW) and numerically controlled oscillator (NCO) phase offsets, which change only when the frequency tuning word FTW\_LOAD\_REQ bit is set.

### <span id="page-28-1"></span>**SERIAL DATA FORMAT**

The instruction byte contains the information shown i[n Table 13.](#page-28-4) 

#### <span id="page-28-4"></span>**Table 13. Serial Port Instruction Word**



R/W, Bit 15 of the instruction word, determines whether a read or a write data transfer occurs after the instruction word write. Logic 1 indicates a read operation, and Logic 0 indicates a write operation.

A14 to A0, Bit I14 to Bit I0 of the instruction word, determine the register that is accessed during the data transfer portion of the communication cycle. For multibyte transfers, A[14:0] is the starting address. The remaining register addresses are generated by the device based on the address increment bit. If the address increment bits are set high (Register 0x000, Bit 5 and Bit 2), multibyte SPI writes start on A[14:0] and increment by 1 every eight bits sent/received. If the address increment bits are set to 0, the address decrements by 1 every eight bits.

### <span id="page-28-2"></span>**SERIAL PORT PIN DESCRIPTIONS Serial Clock (SCLK)**

The serial clock pin synchronizes data to and from the device and runs the internal state machines. The maximum frequency of SCLK is 100 MHz. All data input is registered on the rising edge of SCLK. All data is driven out on the falling edge of SCLK.

### **Chip Select (CS)**

An active low input starts and gates a communication cycle.  $\overline{\text{CS}}$  allows more than one device to be used on the same serial communications lines. The SDIO pin goes to a high impedance state when this input is high. During the communication cycle, the chip select must stay low.

#### **Serial Data I/O (SDIO)**

This pin is a bidirectional data line. In 4-wire mode, this pin acts as the data input and SDO acts as the data output.

### <span id="page-28-3"></span>**SERIAL PORT OPTIONS**

The serial port can support both MSB first and LSB first data formats. This functionality is controlled by the LSB first bit (Register 0x000, Bit 6 and Bit 1). The default is MSB first (LSB  $bit = 0$ ).

When the LSB first bits  $= 0$  (MSB first), the instruction and data bits must be written from MSB to LSB. R/W is followed by A[14:0] as the instruction word, and D[7:0] is the data-word. When the LSB first bits = 1 (LSB first), the opposite is true. A[0:14] is followed by  $R/\overline{W}$ , which is subsequently followed by D[0:7].

The serial port supports a 3-wire or 4-wire interface. When the SDO active bits  $= 1$  (Register 0x000, Bit 4 and Bit 3), a 4-wire interface with a separate input pin (SDIO) and output pin (SDO) is used. When the SDO active bits = 0, the SDO pin is unused and the SDIO pin is used for both the input and the output.

Multibyte data transfers can be performed as well by holding the CS pin low for multiple data transfer cycles (eight SCLKs) after the first data transfer word following the instruction cycle. The first eight SCLKs following the instruction cycle read from or write to the register provided in the instruction cycle. For each additional eight SCLK cycles, the address is either incremented or decremented and the read/write occurs on the new register.

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The direction of the address can be set using ADDRINC or ADDRINC\_M (Register 0x000, Bit 5 and Bit 2). When ADDRINC or ADDRINC\_M is 1, the multicycle addresses are incremented. When ADDRINC or ADDRINC\_M is 0, the addresses are decremented. A new write cycle can always be initiated by bringing CS high and then low again.

To prevent confusion and to ensure consistency between devices, the chip tests the first nibble following the address phase, ignoring the second nibble. This test is completed independently from the LSB first bits and ensures that there are extra clock cycles following the soft reset bits (Register 0x000, Bit 0 and Bit 7). This test of the first nibble only applies when writing to Register 0x000.



<span id="page-29-0"></span>Figure 86. Serial Register Interface Timing, MSB First, Register 0x000, Bit 5 and Bit  $2 = 0$ 



<span id="page-29-1"></span>Figure 88. Timing Diagram for Serial Port Register Read



Figure 89. Timing Diagram for Serial Port Register Write

# <span id="page-30-0"></span>JESD204B SERIAL DATA INTERFACE **JESD204B OVERVIEW**

<span id="page-30-1"></span>The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) has eight JESD204B data ports that receive data. The eight JESD204B ports can be configured as part of a single JESD204B link that uses a single system reference (SYSREF±) and device clock (CLK±).

The JESD204B serial interface hardware consists of three layers: the physical layer, the data link layer, and the transport layer. These sections of the hardware are described in subsequent sections, including information for configuring every aspect of the interface[. Figure 90](#page-30-2) shows the communication layers implemented in the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) serial data interface to recover the clock and deserialize, descramble, and deframe the data before it is sent to the digital signal processing section of the device.

The physical layer establishes a reliable channel between the transmitter (Tx) and the receiver (Rx), the data link layer is responsible for unpacking the data into octets and descrambling the data. The transport layer receives the descrambled JESD204B frames and converts them to DAC samples.

A number of JESD204B parameters (L, F, K, M, N, NP, S, HD) define how the data is packed and tell the device how to turn the serial data into samples. These parameters are defined in detail in th[e Transport Layer](#page-42-0) section. The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) also has a descrambling option (see the [Descrambler](#page-36-0) section for more information).

The various combinations of JESD204B parameters that are supported depend solely on the number of lanes. Thus, a unique set of parameters can be determined by selecting the lane count to be used. In addition, the interpolation rate and number of lanes can be used to define the rest of the configuration needed to set up the [AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf) The interpolation rate and the number of lanes are selected in Register 0x110.

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) has a single DAC output; however, for the purposes of the complex signal processing on chip, the converter count is defined as  $M = 2$  whenever interpolation is used.

For a particular application, the number of converters to use (M) and the DataRate variable are known. The LaneRate variable and number of lanes (L) can be traded off as follows:

DataRate = (DACRate)/(InterpolationFactor)  $LaneRate = (20 \times DataRate \times M)/L$ 

where LaneRate must be between 750 Mbps and 12.5 Gbps.

Achieving and recovering synchronization of the lanes is very important. To simplify the interface to the transmitter, the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) designate a master synchronization signal for each JESD204B link. The SYNCOUT± pin is used as the master signal for all lanes. If any lane in a link loses synchronization, a resynchronization request is sent to the transmitter via the synchronization signal of the link. The transmitter stops sending data and instead sends synchronization characters to all lanes in that link until resynchronization is achieved.



Figure 90. Functional Block Diagram of Serial Link Receiver

#### <span id="page-30-2"></span>**Table 14. Single-Link JESD204B Operating Modes**





#### **Table 15. Data Structure per Lane for JESD204B Operating Modes<sup>1</sup>**

1 Mx is the converter number and Sy is the sample number. For example, M0S0 means Converter 0, Sample 0. Blank cells are not applicable.

#### <span id="page-31-0"></span>**PHYSICAL LAYER**

The physical layer of the JESD204B interface, hereafter referred to as the deserializer, has eight identical channels. Each channel consists of the terminators, an equalizer, a clock and data recovery (CDR) circuit, and the 1:40 demux function (se[e Figure 91\)](#page-31-1).



Figure 91. Deserializer Block Diagram

<span id="page-31-1"></span>JESD204B data is input to the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) via the SERDINx± 1.2 V differential input pins as per the JESD204B specification.

#### **Interface Power-Up and Input Termination**

Before using the JESD204B interface, it must be powered up by setting Register 0x200, Bit  $0 = 0$ . In addition, each physical lane (PHY) that is not being used (SERDINx±) must be powered down. To do so, set the corresponding Bit x for Physical Lane x in Register 0x201 to 0 if the physical lane is being used, and to 1 if it is not being used.

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) autocalibrates the input termination to 50  $\Omega$ . Before running the termination calibration, Register 0x2A7 and Register 0x2AE must be written as described in [Table 16](#page-31-2) to guarantee proper calibration. The termination calibration begins when Register 0x2A7, Bit 0 and Register 0x2AE, Bit 0 transition from low to high. Register 0x2A7 controls autocalibration for PHY 0, PHY 1, PHY 6, and PHY 7. Register 0x2AE controls autocalibration for PHY 2, PHY 3, PHY 4, and PHY 5.

The PHY termination autocalibration routine is as shown in [Table 16.](#page-31-2) 

<span id="page-31-2"></span>



The input termination voltage of the DAC is sourced externally via the VTT\_1P2 pins (K3 and K11). Set  $V_{TT}$ , the termination voltage, by connecting it to VDD\_1P2. It is recommended that the JESD204B inputs be ac-coupled to the JESD204B transmit device using 100 nF capacitors.

The calibration code of the termination can be read from Bits[3:0] in Register 0x2AC (PHY 0, PHY 1, PHY 6, PHY 7) and Register 0x2B3 (PHY 2, PHY 3, PHY 4, PHY 5). If needed, the termination values can be adjusted or set using several registers. The TERM\_BLKx\_CTRLREG1 registers (Register 0x2A8 and Register 0x2AF), can override the autocalibrated value. When set to 0xXXX0XXXX, the termination block autocalibrates, which is the normal, default setting. When set to 0xXXX1XXXX, the autocalibration value is overwritten with the value in Bits[3:1] of Register 0x2A8 and Register 0x2AF. Individual offsets from the autocalibration value for each lane can be programmed in Bits[3:0] of Register 0x2BB to Register 0x2C2. The value is a signed magnitude, with Bit 3 as the sign bit. The total range of the termination resistor value is about 94  $Ω$  to 120  $Ω$ , with approximately 3.5% increments across the range (for example, smaller steps at the bottom of the range than at the top).

#### **Receiver Eye Mask**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) complies with the JESD204B specification regarding the receiver eye mask and is capable of capturing data that complies with this mask[. Figure 92](#page-32-0) shows the receiver eye mask normalized to the data rate interval with a 600 mV  $\mathrm{V_{TT}}$ swing. See the JESD204B specification for more information regarding the eye mask and permitted receiver eye opening.



Figure 92. Receiver Eye Mask for 600 mV V $\pi$  Swing

#### <span id="page-32-0"></span>**Clock Relationships**

The following clocks rates are used throughout the rest of the JESD204B section. The relationship between any of the clocks can be derived from the following equations:

DataRate = (DACRate)/(InterpolationFactor)

LaneRate =  $(20 \times DataRate \times M)/L$ 

ByteRate = LaneRate/10

This relationship comes from 8-bit/10-bit encoding, where each byte is represented by 10 bits.

PCLK Rate = ByteRate/4

The processing clock is used for a quad-byte decoder.

FrameRate = ByteRate/F

where  $F$  is defined as octets per frame per lane.

PCLK Factor = FrameRate/PCLK Rate = 4/F

#### where:

M is the JESD204B parameter for converters per link. L is the JESD204B parameter for lanes per link. F is the JESD204B parameter for octets per frame per lane.

#### **SERDES PLL**

#### **Functional Overview of the SERDES PLL**

The independent SERDES PLL uses integer N techniques to achieve clock synthesis. The entire SERDES PLL is integrated on chip, including the VCO and the loop filter. The SERDES PLL VCO operates over the range of 6 GHz to 12.5 GHz.

In the SERDES PLL, a VCO divider block divides the VCO clock by 2 to generate a 3 GHz to 6.25 GHz quadrature clock for the deserializer cores. This clock is the input to the clock and data recovery block that is described in th[e Clock and Data](#page-33-0)  [Recovery](#page-33-0) section.

The reference clock to the SERDES PLL is always running at a frequency, fREF, that is equal to 1/40 of the lane rate (PCLK Rate). This clock is divided by a DivFactor value (set by SERDES\_PLL\_ DIV\_FACTOR) to deliver a clock to the phase frequency detector (PFD) block that is between 35 MHz and 80 MHz[. Table 17](#page-32-1) includes the respective SERDES\_PLL\_DIV\_FACTOR register settings for each of the desired PLL\_REF\_CLK\_RATE options available.

#### <span id="page-32-1"></span>**Table 17. SERDES PLL Divider Settings**



Register 0x280 controls the synthesizer enable and recalibration.

To enable the SERDES PLL, first set the PLL divider register (see [Table 17\)](#page-32-1). Then enable the SERDES PLL by writing Register 0x280, Bit  $0 = 1$ . If a recalibration is needed, write Register 0x280, Bit  $2 =$ 0b1 and then reset the bit to 0b0. The rising edge of the bit causes a recalibration to begin.

Confirm that the SERDES PLL is working by reading Register 0x281. If Register 0x281, Bit  $0 = 1$ , the SERDES PLL has locked. If Register 0x281, Bit  $3 = 1$ , the SERDES PLL was successfully calibrated. If Register 0x281, Bit 4 or Bit 5 is high, the PLL reaches the lower or upper end of its calibration band and must be recalibrated by writing 0 and then 1 to Register 0x280, Bit 2.

#### <span id="page-33-0"></span>**Clock and Data Recovery**

The deserializer is equipped with a CDR circuit. Instead of recovering the clock from the JESD204B serial lanes, the CDR recovers the clocks from the SERDES PLL. The 3 GHz to 6.25 GHz output from the SERDES PLL, shown in [Figure 94,](#page-33-1) is the input to the CDR.

A CDR sampling mode must be selected to generate the lane rate clock inside the device. If the desired lane rate is greater than 6.25 GHz, half rate CDR operation must be used. If the desired lane rate is less than 6.25 GHz, disable half rate operation. If the lane rate is less than 3 GHz, disable full rate and enable  $2\times$ oversampling to recover the appropriate lane rate clock[. Table 18](#page-33-2) gives a breakdown of CDR sampling settings that must be set depending on the lane rate value.

#### <span id="page-33-2"></span>**Table 18. CDR Operating Modes**



The CDR circuit synchronizes the phase used to sample the data on each serial lane independently. This independent phase adjustment per serial interface ensures accurate data sampling and eases the implementation of multiple serial interfaces on a PCB.

After configuring the CDR circuit, reset it and then release the reset by writing 1 and then 0 to Register 0x206, Bit 0.

#### **Power-Down Unused PHYs**

Note that any unused and enabled lanes consume extra power unnecessarily. Each lane that is not being used (SERDINx±) must be powered off by writing a 1 to the corresponding bit of PHY\_PD (Register 0x201).

#### **Equalization**

To compensate for signal integrity distortions for each PHY channel due to PCB trace length and impedance, the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) employs an easy to use, low power equalizer on each JESD204B channel. The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) equalizers can compensate for insertion losses far greater than required by the JESD204B specification. The equalizers have two modes of operation that are determined by the EQ\_POWER\_MODE register setting in Register 0x268, Bits[7:6]. In low power mode (Register 0x268, Bits[7:6] = 2b'01) and operating at the maximum lane rate of 12.5 Gbps, the equalizer can compensate for up to 11.5 dB of insertion loss. In normal mode (Register 0x268, Bits[7:6] =  $2b$ <sup>2</sup>00), the equalizer can compensate for up to 17.2 dB of insertion loss. This performance is shown in [Figure 93](#page-33-3) as an overlay to the JESD204B specification for insertion loss. [Figure 93](#page-33-3) shows the equalization performance at 12.5 Gbps, near the maximum baud rate for the [AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf) 



<span id="page-33-3"></span>Figure 93. Insertion Loss Allowed

<span id="page-33-1"></span>

Figure 94. SERDES PLL Synthesizer Block Diagram Including VCO Divider Block

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[Figure 95](#page-34-1) and [Figure 96](#page-34-2) are provided as points of reference for hardware designers and show the insertion loss for various lengths of well laid out stripline and microstrip transmission lines, respectively. See th[e Hardware Considerations](#page-48-0) section for specific layout recommendations for the JESD204B channel.

Low power mode is recommended if the insertion loss of the JESD204B PCB channels is less than that of the most lossy supported channel for low power mode (shown i[n Figure 93\)](#page-33-3). If the insertion loss is greater than that, but still less than that of the most lossy supported channel for normal mode (shown in [Figure 93\)](#page-33-3), use normal mode. At 12.5 Gbps operation, the equalizer in normal mode consumes about 4 mW more power per lane used than in low power equalizer mode. Note that either mode can be used in conjunction with transmitter preemphasis to ensure functionality and/or optimize for power.

<span id="page-34-1"></span>

<span id="page-34-2"></span>Figure 96. Insertion Loss of 50 Ω Microstrips on FR4

#### <span id="page-34-0"></span>**DATA LINK LAYER**

The data link layer of the [AD9163 J](http://www.analog.com/AD9163?doc=ad9163.pdf)ESD204B interface accepts the deserialized data from the PHYs and deframes and descrambles them so that data octets are presented to the transport layer to be put into DAC samples. The architecture of the data link layer is shown in [Figure 97.](#page-35-0) The data link layer consists of a synchronization FIFO for each lane, a crossbar switch, a deframer, and a descrambler.

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) can operate as a single-link high speed JESD204B serial data interface. All eight lanes of the JESD204B interface handle link layer communications such as code group synchronization (CGS), frame alignment, and frame synchronization.

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) decodes 8-bit/10-bit control characters, allowing marking of the start and end of the frame and alignment between serial lanes. Eac[h AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) serial interface link can issue a synchronization request by setting its SYNCOUT± signal low. The synchronization protocol follows Section 4.9 of the JESD204B standard. When a stream of four consecutive /K/ symbols is received, the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) deactivates the synchronization request by setting the SYNCOUT± signal high at the next internal LMFC rising edge. Then, the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) waits for the transmitter to issue an initial lane alignment sequence (ILAS). During the ILAS, all lanes are aligned using the /A/ to /R/ character transition as described in th[e JESD204B Serial Link Establishment](#page-35-1) section. Elastic buffers hold early arriving lane data until the alignment character of the latest lane arrives. At this point, the buffers for all lanes are released and all lanes are aligned (see [Figure 98\)](#page-35-2).

<span id="page-35-0"></span>

Figure 98. Lane Alignment During ILAS

#### <span id="page-35-2"></span><span id="page-35-1"></span>**JESD204B Serial Link Establishment**

A brief summary of the high speed serial link establishment process for Subclass 1 is provided. See Section 5.3.3 of the JESD204B specifications document for complete details.

#### **Step 1: Code Group Synchronization**

Each receiver must locate /K/ (K28.5) characters in its input data stream. After four consecutive /K/ characters are detected on all link lanes, the receiver block deasserts the SYNCOUT± signal to the transmitter block at the receiver LMFC edge.

The transmitter captures the change in the  $\overline{\text{SYNCOUT}\pm}$  signal and at a future transmitter LMFC rising edge starts the ILAS.

#### **Step 2: Initial Lane Alignment Sequence**

The main purposes of this phase are to align all the lanes of the link and to verify the parameters of the link.

Before the link is established, write each of the link parameters to the receiver device to designate how data is sent to the receiver block.

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The ILAS consists of four or more multiframes. The last character of each multiframe is a multiframe alignment character, /A/. The first, third, and fourth multiframes are populated with predetermined data values. Note that Section 8.2 of the JESD204B specifications document describes the data ramp that is expected during ILAS. Th[e AD9163 d](http://www.analog.com/AD9163?doc=ad9163.pdf)oes not require this ramp. The deframer uses the final /A/ of each lane to align the ends of the multiframes within the receiver. The second multiframe contains an /R/ (K.28.0), /Q/ (K.28.4), and then data corresponding to the link parameters. Additional multiframes can be added to the ILAS if needed by the receiver. By default, the [AD9163 u](http://www.analog.com/AD9163?doc=ad9163.pdf)ses four multiframes in the ILAS (this can be changed in Register 0x478). If using Subclass 1, exactly four multiframes must be used.

After the last /A/ character of the last ILAS, multiframe data begins streaming. The receiver adjusts the position of the /A/
character such that it aligns with the internal LMFC of the receiver at this point.

#### **Step 3: Data Streaming**

In this phase, data is streamed from the transmitter block to the receiver block.

Optionally, data can be scrambled. Scrambling does not start until the very first octet following the ILAS.

The receiver block processes and monitors the data it receives for errors, including the following:

- Bad running disparity (8-bit/10-bit error)
- Not in table (8-bit/10-bit error)
- Unexpected control character
- Bad ILAS
- Interlane skew error (through character replacement)

If any of these errors exist, they are reported back to the transmitter in one of the following ways (see th[e JESD204B](#page-46-0)  [Error Monitoring](#page-46-0) section for details):

- SYNCOUT± signal assertion: resynchronization (SYNCOUT± signal pulled low) is requested at each error for the last two errors. For the first three errors, an optional resynchronization request can be asserted when the error counter reaches a set error threshold.
- For the first three errors, each multiframe with an error in it causes a small pulse on SYNCOUT±.
- Errors can optionally trigger an interrupt request (IRQ) event, which can be sent to the transmitter.

For more information about the various test modes for verifying the link integrity, see th[e JESD204B Test Modes](#page-44-0) section.

#### **Lane First In/First Out (FIFO)**

The FIFOs in front of the crossbar switch and deframer synchronize the samples sent on the high speed serial data interface with the deframer clock by adjusting the phase of the incoming data. The FIFO absorbs timing variations between the data source and the deframer; this allows up to two PCLK cycles of drift from the transmitter. The FIFO\_STATUS\_REG\_0 register and FIFO\_STATUS\_REG\_1 register (Register 0x30C and Register 0x30D, respectively) can be monitored to identify whether the FIFOs are full or empty.

#### **Lane FIFO IRQ**

An aggregate lane FIFO error bit is also available as an IRQ event. Use Register 0x020, Bit 2 to enable the FIFO error bit, and then use Register 0x024, Bit 2 to read back its status and reset the IRQ signal. See the [Interrupt Request Operation](#page-57-0) section for more information.

#### **Crossbar Switch**

Register 0x308 to Register 0x30B allow arbitrary mapping of physical lanes (SERDINx±) to logical lanes used by the SERDES deframers.



Write each SRC\_LANEy with the number (x) of the desired physical lane (SERDINx±) from which to obtain data. By default, all logical lanes use the corresponding physical lane as their data source. For example, by default, SRC\_LANE0 = 0; therefore, Logical Lane 0 obtains data from Physical Lane 0 (SERDIN0±). To use SERDIN4± as the source for Logical Lane 0 instead, the user must write SRC\_LANE0 = 4.

#### **Lane Inversion**

Register 0x334 allows inversion of desired logical lanes, which can be used to ease routing of the SERDINx± signals. For each Logical Lane x, set Bit x of Register 0x334 to 1 to invert it.

#### **Deframer**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) consists of one quad-byte deframer (QBD). The deframer accepts the 8-bit/10-bit encoded data from the deserializer (via the crossbar switch), decodes it, and descrambles it into JESD204B frames before passing it to the transport layer to be converted to DAC samples. The deframer processes four symbols (or octets) per processing clock (PCLK) cycle.

The deframer uses the JESD204B parameters that the user has programmed into the register map to identify how the data is packed, and unpacks it. The JESD204B parameters are described in detail in the [Transport Layer](#page-42-0) section; many of the parameters are also needed in the transport layer to convert JESD204B frames into samples.

#### **Descrambler**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) provides an optional descrambler block using a self synchronous descrambler with the following polynomial:  $1 + x^{14} + x^{15}$ .

Enabling data scrambling reduces spectral peaks that are produced when the same data octets repeat from frame to frame. It also makes the spectrum data independent so that possible frequency selective effects on the electrical interface do not cause data dependent errors. Descrambling of the data is enabled by setting the SCR bit (Register 0x453, Bit 7) to 1.

# **Syncing LMFC Signals**

The first step in guaranteeing synchronization across links and devices begins with syncing the LMFC signals. In Subclass 0, the LMFC signal is synchronized to an internal processing clock. In Subclass 1, LMFC signals are synchronized to an external SYSREF± signal.

# **SYSREF± Signal**

The SYSREF± signal is a differential source synchronous input that synchronizes the LMFC signals in both the transmitter and receiver in a JESD204B Subclass 1 system to achieve deterministic latency.

The SYSREF± signal is a rising edge sensitive signal that is sampled by the device clock rising edge. It is best practice that the device clock and SYSREF± signals be generated by the same source, such as th[e HMC7044](http://www.analog.com/hmc7044?doc=AD9163.pdf) clock generator, so that the phase alignment between the signals is fixed. When designing for optimum deterministic latency operation, consider the timing distribution skew of the SYSREF± signal in a multipoint link system (multichip).

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) supports a periodic SYSREF± signal. The periodicity can be continuous, strobed, or gapped periodic. The SYSREF± signal can always be dc-coupled (with a common-mode voltage of 0 V to 1.25 V). When dc-coupled, a small amount of commonmode current (<500 µA) is drawn from the SYSREF± pins. See [Figure 99](#page-37-0) for the SYSREF± internal circuit.

To avoid this common-mode current draw, use a 50% duty cycle periodic SYSREF± signal with ac coupling capacitors. If ac-coupled, the ac coupling capacitors combine with the resistors shown in [Figure 99](#page-37-0) to make a high-pass filter with an RC time constant of  $\tau$  = RC. Select C such that  $\tau$  > 4/SYSREF ± frequency. In addition, the edge rate must be sufficiently fast to meet the SYSREF± vs. DAC clock keep out window (KOW) requirements.

It is possible to use ac-coupled mode without meeting the frequency to time constant constraints ( $\tau$  = RC and  $\tau$  > 4/SYSREF $\pm$ frequency) by using SYSREF± hysteresis (Register 0x088 and Register 0x089). However, using hystereis increases the DAC clock KOW [\(Table 6 d](#page-6-0)oes not apply) by an amount depending on the SYSREF± frequency, level of hysteresis, capacitor choice, and edge rate.



<span id="page-37-0"></span>

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) supports several LMFC sync processing modes. These modes are one-shot, continuous, and monitor modes.

All sync processing modes perform a phase check to confirm that the LMFC is phase aligned to an alignment edge. In Subclass 1, the SYSREF± rising edge acts as the alignment edge; in Subclass 0, an internal processing clock acts as the alignment edge.

The SYSREF± signal is sampled by a divide by 4 version of the DAC clock. After SYSREF± is sampled, the phase of the DAC clock/4 used to sample SYSREF± is stored in Register 0x037, Bits[7:0] and Register 0x038, Bits[3:0] as a thermometer code. This offset can be used by the SERDES data transmitter (for example, FPGA) to align multiple DACs by accounting for this clock offset when transmitting data. See th[e Sync Procedure s](#page-37-1)ection for details on the procedure for syncing the LMFC signals.

## **One-Shot Sync Mode (SYNC\_MODE = Register 0x03A, Bits[1:0] = 0b10)**

In one-shot sync mode, a phase check occurs on only the first alignment edge that is received after the sync machine is armed. After the phase is aligned on the first edge, th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) transitions to monitor mode. Though an LMFC synchronization occurs only once, the SYSREF± signal can still be continuous. In this case, the phase is monitored and reported, but no clock phase adjustment occurs.

## **Continuous Sync Mode (SYNC\_MODE = Register 0x03A, Bits[1:0] = 0b01)**

Continuous mode must be used in Subclass 1 only with a periodic SYSREF± signal. In continuous mode, a phase check/alignment occurs on every alignment edge.

Continuous mode differs from one-shot mode in two ways. First, no SPI cycle is required to arm the device; the alignment edge seen after continuous mode is enabled results in a phase check. Second, a phase check occurs on every alignment edge in continuous mode.

# **Monitor Sync Mode (SYNC\_MODE = Register 0x03A, Bits[1:0]) = 0b00)**

In monitor mode, the user can monitor the phase error in real time. Use this sync mode with a periodic SYSREF± signal. The phase is monitored and reported, but no clock phase adjustment occurs.

When an alignment request (SYSREF± edge) occurs, snapshots of the last phase error are placed into readable registers for reference (Register 0x037 and Register 0x038, Bits[3:0]), and the IRQ\_SYSREF\_JITTER interrupt is set, if appropriate.

# <span id="page-37-1"></span>**Sync Procedure**

The procedure for enabling the sync is as follows:

- 1. Set up the DAC; the SERDES PLL locks it, and enables the CDR (see th[e Start-Up Sequence s](#page-66-0)ection).
- 2. Set Register 0x039 (SYSREF± jitter window). A minimum of 4 DAC clock cycles is recommended. See [Table 21](#page-38-0) for settings.
- 3. Optionally, read back the SYSREF± count to check whether the SYSREF± pulses are being received.

# Data Sheet **AD9163**

- a. Set Register  $0x036 = 0$ . Writing anything to SYSREF\_COUNT resets the count.
- b. Set Register  $0x034 = 0$ . Writing anything to SYNC\_LMFC\_STAT0 saves the data for readback and registers the count.
- c. Read SYSREF\_COUNT from the value from Register 0x036.
- 4. Perform a one-shot sync.
	- a. Set Register  $0x03A = 0x00$ . Clear one-shot mode if already enabled.
	- b. Set Register  $0x03A = 0x02$ . Enable one-shot sync mode. The state machine enters monitor mode after a sync occurs.
- 5. Optionally, read back the sync SYNC\_LMFC\_STATx registers to verify that sync completed correctly.
	- Set Register  $0x034 = 0$ . Register  $0x034$  must be written to read the value.
	- b. Read Register 0x035 and Register 0x034 to find the value of SYNC\_LMFC\_STATx. It is recommended to set SYNC\_LMFC\_STATx to 0 but it can be set to 4, or a LMFC period in DAC clocks – 4, due to jitter.
- 6. Optionally, read back the sync SYSREF\_PHASEx register to identify which phase of the divide by 4 was used to sample SYSREF±. Read Register 0x038 and Register 0x037 as thermometer code. The MSBs of Register 0x037, Bits[7:4], normally show the thermometer code value.
- 7. Turn the link on (Register 0x300, Bit  $0 = 1$ ).
- 8. Read back Register 0x302 (dynamic link latency).
- 9. Repeat the reestablishment of the link several times (Step 1 to Step 7) and note the dynamic link latency values. Based on the values, program the LMFC delay (Register 0x304) and the LMFC variable (Register 0x306), and then restart the link.

#### **Table 20. Sync Processing Modes**



# <span id="page-38-0"></span>**Table 21. SYSREF± Jitter Window Tolerance**



 $1$  The two least significant digits are ignored because the SYSREF $\pm$  signal is sampled with a divide by 4 version of the DAC clock. As a result, the jitter window is set by this divide by 4 clock rather than the DAC clock. It is recommended that at least a four-DAC clock SYSREF± jitter window be chosen.

# **Deterministic Latency**

JESD204B systems contain various clock domains distributed throughout its system. Data traversing from one clock domain to a different clock domain can lead to ambiguous delays in the JESD204B link. These ambiguities lead to nonrepeatable latencies across the link from power cycle to power cycle with each new link establishment. Section 6 of the JESD204B specification addresses the issue of deterministic latency with mechanisms defined as Subclass 1 and Subclass 2.

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) supports JESD204B Subclass 0 and Subclass 1 operation, but not Subclass 2. Write the subclass to Register 0x458, Bits[7:5].

### **Subclass 0**

This mode gives deterministic latency to within 32 DAC clock cycles. It does not require any signal on the SYSREF± pins, which can be left disconnected.

Subclass 0 still requires that all lanes arrive within the same LMFC cycle and the dual DACs must be synchronized to each other.

### **Subclass 1**

This mode gives deterministic latency and allows the link to be synced to within four DAC clock periods. It requires an external SYSREF± signal that is accurately phase aligned to the DAC clock.

### **Deterministic Latency Requirements**

Several key factors are required for achieving deterministic latency in a JESD204B Subclass 1 system.

- SYSREF± signal distribution skew within the system must be less than the desired uncertainty.
- SYSREF± setup and hold time requirements must be met for each device in the system.
- The total latency variation across all lanes, links, and devices must be ≤10 PCLK periods, which includes both variable delays and the variation in fixed delays from lane to lane, link to link, and device to device in the system.



Figure 100. JESD204B Link Delay = Fixed Delay + Variable Delay

# <span id="page-39-0"></span>**Link Delay**

The link delay of a JESD204B system is the sum of the fixed and variable delays from the transmitter, channel, and receiver as shown in [Figure 100.](#page-39-0)

For proper functioning, all lanes on a link must be read during the same LMFC period. Section 6.1 of the JESD204B specification states that the LMFC period must be larger than the maximum link delay. For the [AD9163,](http://www.analog.com/AD9163?doc=ad9163.pdf) this is not necessarily the case; instead, the  $AD9163$  uses a local LMFC for each link (LMFC $_{Rx}$ ) that can be delayed from the SYSREF± aligned LMFC. Because the LMFC is periodic, this delay can account for any amount of fixed delay. As a result, the LMFC period must only be larger than the variation in the link delays, and the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) can achieve proper performance with a smaller total latency[. Figure 101](#page-39-1) and [Figure 102](#page-39-2) show a case where the link delay is greater than an LMFC period. Note that it can be accommodated by delaying  $LMFC_{Rx}$ .

<span id="page-39-1"></span>

<span id="page-39-2"></span>The method to select the LMFCDel (Register 0x304) and LMFCVar (Register 0x306) variables is described in th[e Link](#page-39-3)  [Delay Setup Example, With Known Delays](#page-39-3) section.

Setting LMFCDel appropriately ensures that all the corresponding data samples arrive in the same LMFC period. Then LMFCVar is written into the receive buffer delay (RBD) to absorb all link delay variation. This write ensures that all data samples have arrived before reading. By setting these to fixed values across runs and devices, deterministic latency is achieved.

The RBD described in the JESD204B specification takes values from 1 frame clock cycle to K frame clock cycles, and the RBD of the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) takes values from 0 PCLK cycle to 10 PCLK cycles. As a result, up to 10 PCLK cycles of total delay variation can be absorbed. LMFCVar and LMFCDel are both in PCLK cycles. The PCLK factor, or number of frame clock cycles per PCLK cycle, is equal to 4/F. For more information on this relationship, see the [Clock Relationships](#page-32-0) section.

Two examples follow that show how to determine LMFCVar and LMFCDel. After they are calculated, write LMFCDel into Register 0x304 for all devices in the system, and write LMFCVar to Register 0x306 for all devices in the system.

#### <span id="page-39-3"></span>**Link Delay Setup Example, With Known Delays**

All the known system delays can be used to calculate LMFCVar and LMFCDel.

The example shown i[n Figure 103](#page-40-0) is demonstrated in the following steps. Note that this example is in Subclass 1 to achieve deterministic latency, which has a PCLK factor (4/F) of 2 frame clock cycles per PCLK cycle, and uses K = 32 (frames/multiframe). Because PCBFixed << PCLK Period, PCBFixed is negligible in this example and not included in the calculations.

1. Find the receiver delays using [Table 7.](#page-7-0) RxFixed = 12 PCLK cycles

 $RxVar = 2$  PCLK cycles

2. Find the transmitter delays. The equivalent table in the example JESD204B core (implemented on a GTH or GTX gigabit transceiver on a Virtex-6 FPGA) states that the delay is  $56 \pm 2$  byte clock cycles.

# Data Sheet **AD9163**

- 3. Because the PCLK Rate = ByteRate/4 as described in the [Clock Relationships](#page-32-0) section, the transmitter delays in PCLK cycles are calculated as follows:  $TxFixed = 54/4 = 13.5$  PCLK cycles  $TxVar = 4/4 = 1$  PCLK cycle
- 4. Calculate MinDelayLane as follows:  $MinDelayLane = floor(RxFixed + TxFixed + PCBFixed)$  $=$  floor(12 + 13.5 + 0)  $=$  floor(25.5)

MinDelayLane = 25

5. Calculate MaxDelayLane as follows:  $MaxDelayLane = ceiling(RxFixed + RxVar + TxFixed +$ TxVar + PCBFixed))

$$
= ceiling(12 + 2 + 13.5 + 1 + 0)
$$

$$
= ceiling(28.5)
$$

- MaxDelayLane = 29
- 6. Calculate LMFCVar as follows:  $LMFCVar = (MaxDelay + 1) - (MinDelay - 1)$  $=(29 + 1) - (25 - 1) = 30 - 24$ 
	- LMFCVar = 6 PCLK cycles
- 7. Calculate LMFCDel as follows:  $LMFCDel = (MinDelay - 1) % (K/PClockFactor)$  $= (30 - 1)$  %  $(32/2)$  $= 29 %16$ LMFCDel = 13 PCLK cycles
- Write LMFCDel to Register 0x304 for all devices in the system. Write LMFCVar to Register 0x306 for all devices in the system.

# **Link Delay Setup Example, Without Known Delay**

If the system delays are not known, th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) can read back the link latency between  $LMFC_{RX}$  for each link and the SYSREF± aligned LMFC. This information is then used to calculate LMFCVar and LMFCDel.

[Figure 105](#page-41-0) shows how DYN\_LINK\_LATENCY\_0 (Register 0x302) provides a readback showing the delay (in PCLK cycles) between LMFC<sub>RX</sub> and the transition from ILAS to the first data sample. By repeatedly power cycling and taking this measurement, the minimum and maximum delays across power cycles can be determined and used to calculate LMFCVar and LMFCDel.

I[n Figure 105,](#page-41-0) for Link A, Link B, and Link C, the system containing the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) (including the transmitter) is power cycled and configured 20 times. Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is configured as described in the [Sync Procedure](#page-37-1) section. Because the purpose of this exercise is to determine LMFCDel and LMFCVar, the LMFCDel value is programmed to 0 and the

DYN\_LINK\_LATENCY\_0 value is read from Register 0x302. The variation in the link latency over the 20 runs is shown in [Figure 105,](#page-41-0) described as follows:

- Link A gives readbacks of 6, 7, 0, and 1. Note that the set of recorded delay values rolls over the edge of a multiframe at the boundary of K/PCLK factor = 8. Add the number of PCLK cycles per multiframe = 8 to the readback values of 0 and 1 because they rolled over the edge of the multiframe. Delay values range from 6 to 9.
- Link B gives delay values from 5 to 7.
- Link C gives delay values from 4 to 7.



<span id="page-40-0"></span>Figure 103. LMFC Delay Calculation Example

The example shown i[n Figure 105](#page-41-0) is demonstrated in the following steps. Note that this example is in Subclass 1 to achieve deterministic latency, which has a PCLK factor (FrameRate  $\div$  PCLK Rate) of 4 and uses K = 32; therefore PCLK cycles per multiframe = 8.

- 1. Calculate the minimum of all delay measurements across all power cycles, links, and devices as follows:  $MinDelay = min(all Delay values) = 4$
- 2. Calculate the maximum of all delay measurements across all power cycles, links, and devices as follows:  $MaxDelay = max(all Delay values) = 9$
- 3. Calculate the total delay variation (with guard band) across all power cycles, links, and devices as follows:

 $LMFCVar = (MaxDelay + 1) - (MinDelay - 1)$  $=(9 + 1) - (4 - 1) = 10 - 3 = 7$  PCLK cycles

4. Calculate the minimum delay in PCLK cycles (with guard band) across all power cycles, links, and devices as follows:  $LMFCDel = (MinDelay - 1) % (K/PCLK Factor)$ 

$$
= (I\{11, I\} \times 32/4)
$$
  
= (4 - 1) % 32/4

$$
= 3\% 8 = 3
$$
 PCLK cycles

5. Write LMFCDel to Register 0x304 for all devices in the system. Write LMFCVar to Register 0x306 for all devices in the system.



<span id="page-41-0"></span>Figure 105. Multilink Synchronization Settings, Derived Method Example

# <span id="page-42-0"></span>**TRANSPORT LAYER**



Figure 106. Transport Layer Block Diagram

The transport layer receives the descrambled JESD204B frames and converts them to DAC samples based on the programmed JESD204B parameters shown in [Table 22.](#page-42-1) The device parameters are defined in [Table](#page-42-2) 23.

#### <span id="page-42-1"></span>**Table 22. JESD204B Transport Layer Parameters**





# <span id="page-42-2"></span>**Table 23. JESD204B Device Parameters**

Certain combinations of these parameters are supported by the [AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf) Se[e Table 26](#page-43-0) for a list of supported interpolation rates and the number of lanes that is supported for each rate. [Table 26](#page-43-0) lists the JESD204B parameters for each of the interpolation and number of lanes configuration, and gives an example lane rate for a 5 GHz DAC clock[. Table 25](#page-42-3) lists JESD204B parameters that have fixed values. A value of yes i[n Table](#page-42-4) 24 means the interpolation rate is supported for the number of lanes. A blank cell means it is not supported.

### <span id="page-42-4"></span>**Table 24. Interpolation Rates and Number of Lanes**



#### <span id="page-42-3"></span>**Table 25. JESD204B Parameters with Fixed Values**





<span id="page-43-0"></span>

# **Configuration Parameters**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) modes refer to the link configuration parameters for L, K, M, N, NP, S, and F. [Table 27](#page-44-1) provides the description and addresses for these settings.

<span id="page-44-1"></span>



# **Data Flow Through the JESD204B Receiver**

The link configuration parameters determine how the serial bits on the JESD204B receiver interface are deframed and passed on to the DACs as data samples.

# **Deskewing and Enabling Logical Lanes**

After proper configuration, the logical lanes are automatically deskewed. All logical lanes are enabled or not based on the lane number setting in Register 0x110, Bits[7:4]. The physical lanes are all powered up by default.

To disable power to physical lanes that are not being used, set Bit x in Register 0x201 to 1 to disable Physical Lane x, and keep it at 0 to enable it.

# <span id="page-44-0"></span>**JESD204B TEST MODES**

#### **PHY PRBS Testing**

The JESD204B receiver on th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) includes a PRBS pattern checker on the back end of its physical layer. This functionality enables bit error rate (BER) testing of each physical lane of the JESD204B link. The PHY PRBS pattern checker does not require that the JESD204B link be established. It can synchronize with a PRBS7, PRBS15, or PRBS31 data pattern. PRBS pattern verification can be done on multiple lanes at once. The error

counts for failing lanes are reported for one JESD204B lane at a time. The process for performing PRBS testing on the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is as follows:

- 1. Start sending a PRBS7, PRBS15, or PRBS31 pattern from the JESD204B transmitter.
- 2. Select and write the appropriate PRBS pattern to Register 0x316, Bits[3:2], as shown in [Table 28.](#page-44-2)
- 3. Enable the PHY test for all lanes being tested by writing to PHY\_TEST\_EN (Register 0x315). Each bit of Register 0x315 enables the PRBS test for the corresponding lane. For example, writing a 1 to Bit 0 enables the PRBS test for Physical Lane 0.
- 4. Toggle PHY\_TEST\_RESET (Register 0x316, Bit 0) from 0 to 1 then back to 0.
- 5. Set PHY\_PRBS\_TEST\_THRESHOLD\_xBITS (Bits[23:0], Register 0x319 to Register 0x317) as desired.
- 6. Write a 0 and then a 1 to PHY\_TEST\_START (Register 0x316, Bit 1). The rising edge of PHY\_TEST\_START starts the test.
	- a. (Optional) In some cases, it may be necessary to repeat Step 4 at this point. Toggle PHY\_TEST\_RESET (Register 0x316, Bit 0) from 0 to 1, then back to 0.
- 7. Wait 500 ms.
- 8. Stop the test by writing PHY\_TEST\_START (Register 0x316, Bit  $1$ ) = 0.
- 9. Read the PRBS test results.
	- a. Each bit of PHY\_PRBS\_PASS (Register 0x31D) corresponds to one SERDES lane  $(0 = \text{fail}, 1 = \text{pass})$ .

The number of PRBS errors seen on each failing lane can be read by writing the lane number to check (0 to 7) in PHY\_SRC\_ ERR\_CNT (Register 0x316, Bits[6:4]) and reading the PHY\_PRBS\_ ERR\_COUNT (Register 0x31C to Register 0x31A). The maximum error count is 2<sup>24-1</sup>. If all bits of Register 0x31C to Register 0x31A are high, the maximum error count on the selected lane is exceeded.

#### <span id="page-44-2"></span>**Table 28. PHY PRBS Pattern Selection**



#### **Transport Layer Testing**

The JESD204B receiver in th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) supports the short transport layer (STPL) test as described in the JESD204B standard. This test can be used to verify the data mapping between the JESD204B transmitter and receiver. To perform this test, this function must be implemented in the logic device and enabled there. Before running the test on the receiver side, the link must be established and running without errors.

The STPL test ensures that each sample from each converter is mapped appropriately according to the number of converters (M) and the number of samples per converter (S). As specified in the JESD204B standard, the converter manufacturer specifies what test samples are transmitted. Each sample must have a

unique value. For example, if  $M = 2$  and  $S = 2$ , four unique samples are transmitted repeatedly until the test is stopped. The expected sample must be programmed into the device and the expected sample is compared to the received sample one sample at a time until all are tested. The process for performing this test on the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is described as follows:

- 1. Synchronize the JESD204B link.
- 2. Enable the STPL test at the JESD204B Tx.
- 3. Depending on JESD204B case, there may be up to two DACs, and each frame may contain up to four DAC samples. Configure the SHORT\_TPL\_REF\_SP\_MSB bits (Register 0x32E) and SHORT\_TPL\_REF\_SP\_LSB bits (Register 0x32D) to match one of the samples for one converter within one frame.
- 4. Set SHORT\_TPL\_SP\_SEL (Register 0x32C, Bits[7:4]) to select the sample within one frame for the selected converter according t[o Table 29.](#page-45-0)
- 5. Set SHORT\_TPL\_TEST\_EN (Register 0x32C, Bit 0) to 1.
- 6. Set SHORT\_TPL\_TEST\_RESET (Register 0x32C, Bit 1) to 1, then back to 0.
- 7. Wait for the desired time. The desired time is calculated as  $1/(sample rate \times BER)$ . For example, given a bit error rate of BER =  $1 \times 10^{-10}$  and a sample rate = 1 GSPS, the desired time  $= 10$  sec.
- 8. Read the test result at SHORT\_TPL\_FAIL (Register 0x32F, Bit 0).
- 9. Choose another sample for the same or another converter to continue with the test, until all samples for both converters from one frame are verified. (Note that the converter count is  $M = 2$  for all interpolator modes on the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) to enable complex signal processing.)

Consult [Table 29](#page-45-0) for a guide to the test sample alignment. Note that the sample order for 1×, eight-lane mode has Sample 1 and Sample 2 swapped. Also, the STPL test for the three-lane and six-lane options is not functional and always fails.



<sup>1</sup> Mx is the converter number and Sy is the sample number. For example, M0S0 means Converter 0, Sample 0. SPx is the sample pattern word number. For example, SP0 means Sample Pattern Word 0.

#### <span id="page-45-0"></span>**Table 29. Short TPL Test Samples Assignment<sup>1</sup>**

# **Repeated CGS and ILAS Test**

As per Section 5.3.3.8.2 of the JESD204B specification, the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) can check that a constant stream of /K28.5/ characters is being received, or that CGS followed by a constant stream of ILAS is being received.

To run a repeated CGS test, send a constant stream of /K28.5/ characters to the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) SERDES inputs. Next, set up the device and enable the links. Ensure that the /K28.5/ characters are being received by verifying that SYNCOUT± is deasserted and that CGS has passed for all enabled link lanes by reading Register 0x470.

To run the CGS followed by a repeated ILAS sequence test, follow the procedure to set up the links, but before performing the last write (enabling the links), enable the ILAS test mode by writing a 1 to Register 0x477, Bit 7. Then, enable the links. When the device recognizes four CGS characters on each lane, it deasserts the SYNCOUT±. At this point, the transmitter starts sending a repeated ILAS sequence.

Read Register 0x473 to verify that initial lane synchronization has passed for all enabled link lanes.

# <span id="page-46-0"></span>**JESD204B ERROR MONITORING**

#### **Disparity, Not in Table, and Unexpected Control (K) Character Errors**

As per Section 7.6 of the JESD204B specification, th[e AD9163](http://www.analog.com/AD9163?doc=AD9163.pdf) can detect disparity errors, not in table (NIT) errors, and unexpected control character errors, and can optionally issue a sync request and reinitialize the link when errors occur.

Note that the disparity error counter counts all characters with invalid disparity, regardless of whether they are in the 8-bit/10-bit decoding table. This is a minor deviation from the JESD204B specification, which only counts disparity errors when they are in the 8-bit/10-bit decoding table.

Several other interpretations of the JESD204B specification are noted in this section. When three NIT errors are injected to one lane and QUAL\_RDERR (Register  $0x476$ , Bit  $4$ ) = 1, the readback values of the bad disparity error (BDE) count register is 1. Reporting of disparity errors that occur at the same character position of an NIT error is disabled. No such disabling is performed for the disparity errors in the characters after an NIT error. Therefore, it is expected behavior that an NIT error may result in a BDE error.

A resync is triggered when four NIT errors are injected with Register 0x476, Bit  $4 = 1$ . When this bit is set, the error counter does not distinguish between a concurrent invalid symbol with the wrong running disparity but is in the 8-bit/10-bit decoding table, and an NIT error. Thus, a resync can be triggered when four NIT errors are injected because they are not distinguished from disparity errors.

#### **Checking Error Counts**

The error count can be checked for disparity errors, NIT errors, and unexpected control character errors. The error counts are

on a per lane and per error type basis. Each error type and lane has a register dedicated to it. To check the error count, the following steps must be performed:

- 1. Choose and enable which errors to monitor by selecting them in Register 0x480, Bits[5:3] to Register 0x487, Bits[5:3]. Unexpected K (UEK) character, BDE, and NIT error monitoring can be selected for each lane by writing a 1 to the appropriate bit, as described in the register map. These bits are enabled by default.
- 2. The corresponding error counter reset bits are in Register 0x480, Bits[2:0] to Register 0x487, Bits[2:0]. Write a 0 to the corresponding bit to reset that error counter.
- 3. Registers 0x488, Bits[2:0] to Register 0x48F, Bits[2:0] have the terminal count hold indicator for each error counter. If this flag is enabled, when the terminal error count of 0xFF is reached, the counter ceases counting and holds that value until reset. Otherwise, it wraps to 0x00 and continues counting. Select the desired behavior and program the corresponding register bits per lane.

#### **Check for Error Count Over Threshold**

To check for the error count over threshold, follow these steps:

- 1. Define the error counter threshold. The error counter threshold can be set to a user defined value in Register 0x47C, or left to the default value of 0xFF. When the error threshold is reached, an IRQ is generated or SYNCOUT± is asserted or both, depending on the mask register settings. This one error threshold is used for all three types of errors (UEK, NIT, and BDE).
- 2. Set the SYNC\_ASSERT\_MASK bits. The SYNCOUT± assertion behavior is set in Register 0x47D, Bits[2:0]. By default, when any error counter of any lane is equal to the threshold, it asserts  $SYNCOUT \pm (Register 0x47D, Bits[2:0] =$ 0b111).
- 3. Read the error count reached indicator. Each error counter has a terminal count reached indicator, per lane. This indicator is set to 1 when the terminal count of an error counter for a particular lane has been reached. These status bits are located in Register 0x490, Bits[2:0] to Register 0x497, Bits[2:0]. These registers also indicate whether a particular lane is active by setting Bit  $3 = 0b1$ .

#### <span id="page-46-1"></span>**Error Counter and IRQ Control**

For error counter and IRQ control, follow these steps:

1. Enable the JESD204B interrupts. The interrupts for the UEK, NIT, and BDE error counters are in Register 0x4B8, Bits[7:5]. There are other interrupts to monitor when bringing up the link, such as lane deskewing, initial lane sync, good check sum, frame sync, code group sync (Register 0x4B8, Bits[4:0], and configuration mismatch (Register 0x4B9, Bit 0). These bits are off by default but can be enabled by writing 0b1 to the corresponding bit.

- 2. Read the JESD204B interrupt status. The interrupt status bits are in Register 0x4BA, Bits[7:0] and Register 0x4BB, Bit 0, with the status bit position corresponding to the enable bit position.
- 3. It is recommended to enable all interrupts that are planned to be used prior to bringing up the JESD204B link. When the link is up, the interrupts can be reset and then used to monitor the link status.

# **Monitoring Errors via SYNCOUT±**

When one or more disparity, NIT, or unexpected control character errors occur, the error is reported on the SYNCOUT± pin as per Section 7.6 of the JESD204B specification. The JESD204B specification states that the SYNCOUT± signal is asserted for exactly two frame periods when an error occurs. For the [AD9163,](http://www.analog.com/AD9163?doc=ad9163.pdf) the width of the SYNCOUT ± pulse can be programmed to ½, 1, or 2 PCLK cycles. The settings to achieve a SYNCOUT± pulse of two frame clock cycles are given in Table 30.

#### <span id="page-47-0"></span>**Table 30. Setting SYNCOUT± Error Pulse Duration**



<sup>1</sup> These register settings assert the  $\overline{\mathsf{SYNCOUT}\pm}$  signal for two frame clock cycle pulse widths.

#### **Unexpected Control Character, NIT, Disparity IRQs**

For UEK character, NIT, and disparity errors, error count over the threshold events are available as IRQ events. Enable these events by writing to Register 0x4B8, Bits[7:5]. The IRQ event status can be read at Register 0x4BA, Bits[7:5] after the IRQs are enabled.

See the [Error Counter and IRQ Control](#page-46-1) section for information on resetting the IRQ. See th[e Interrupt Request Operation](#page-57-0) section for more information on IRQs.

#### **Errors Requiring Reinitializing**

A link reinitialization automatically occurs when four invalid disparity characters are received as per Section 7.1 of the JESD204B specification. When a link reinitialization occurs, the resync request is five frames and nine octets long.

The user can optionally reinitialize the link when the error count for disparity errors, NIT errors, or UEK character errors reaches a programmable error threshold. The process to enable the reinitialization feature for certain error types is as follows:

1. Choose and enable which errors to monitor by selecting them in Register 0x480, Bits[5:3] to Register 0x487, Bits[5:3]. UEK, BDE, and NIT error monitoring can be selected for each lane by writing a 1 to the appropriate bit, as described in [Table 44.](#page-75-0) These are enabled by default.

- 2. Enable the sync assertion mask for each type of error by writing to SYNC\_ASSERT\_MASK (Register 0x47D, Bits[2:0]) according to [Table 31.](#page-47-1)
- 3. Program the desired error counter threshold into ERRORTHRES (Register 0x47C).
- 4. For each error type enabled in the SYNC\_ASSERT\_MASK register, if the error counter on any lane reaches the programmed threshold, SYNCOUT± falls, issuing a sync request. Note that all error counts are reset when a link reinitialization occurs. The IRQ does not reset and must be reset manually.



# <span id="page-47-1"></span>**Table 31. Sync Assertion Mask (SYNC\_ASSERT\_MASK)**

### **CGS, Frame Sync, Checksum, and ILAS Monitoring**

Register 0x470 to Register 0x473 can be monitored to verify that each stage of the JESD204B link establishment has occurred.

Bit x of CODE\_GRP\_SYNC (Register 0x470) is high if Link Lane x received at least four K28.5 characters and passed code group synchronization.

Bit x of FRAME\_SYNC (Register 0x471) is high if Link Lane x completed initial frame synchronization.

Bit x of GOOD\_CHECKSUM (Register 0x472) is high if the checksum sent over the lane matches the sum of the JESD204B parameters sent over the lane during ILAS for Link Lane x. The parameters can be added either by summing the individual fields in registers or summing the packed register. If Register 0x300, Bit  $6 = 0$  (default), the calculated checksums are the lower eight bits of the sum of the following fields: DID, BID, LID, SCR, L − 1, F − 1, K − 1, M − 1, N − 1, SUBCLASSV, NP − 1, JESDV, S − 1, and HD. If Register 0x300, Bit  $6 = 1$ , the calculated checksums are the lower eight bits of the sum of Register 0x400 to Register 0x40C and LID.

Bit x of INIT\_LANE\_SYNC (Register 0x473) is high if Link Lane x passed the initial lane alignment sequence.

### **CGS, Frame Sync, Checksum, and ILAS IRQs**

Fail signals for CGS, frame sync, checksum, and ILAS are available as IRQ events. Enable them by writing to Register 0x4B8, Bits[3:0]. The IRQ event status can be read at Register 0x4BA, Bits[3:0] after the IRQs are enabled. Write a 1 to Register 0x4BA, Bit 0 to reset the CGS IRQ. Write a 1 to Register 0x4BA, Bit 1 to reset the frame sync IRQ. Write a 1 to Register 0x4BA, Bit 2 to reset the checksum IRQ. Write a 1 to Register 0x4BA, Bit 3 to reset the ILAS IRQ.

See the [Interrupt Request Operation](#page-57-0) section for more information.

#### **Configuration Mismatch IRQ**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) has a configuration mismatch flag that is available as an IRQ event. Use Register 0x4B9, Bit 0 to enable the mismatch flag (it is enabled by default), and then use Register 0x4BB, Bit 0 to read back its status and reset the IRQ signal. See the [Interrupt](#page-57-0)  [Request Operation](#page-57-0) section for more information.

The configuration mismatch event flag is high when the link configuration settings (in Register 0x450 to Register 0x45D) do not match the JESD204B transmitted settings (Register 0x400 to Register 0x40D).

This function is different from the good checksum flags in Register 0x472. The good checksum flags ensure that the transmitted checksum matches a calculated checksum based on the transmitted settings. The configuration mismatch event ensures that the transmitted settings match the configured settings.

# **HARDWARE CONSIDERATIONS**

See the [Applications Information](#page-58-0) section for information on hardware considerations.

# MAIN DIGITAL DATAPATH



Figure 107. Block Diagram of the Main Digital Datapath

<span id="page-49-0"></span>The block diagram i[n Figure 107](#page-49-0) shows the functionality of the main digital datapath. The digital processing includes an input interpolation block with the choice of bypass  $(1\times)$ , 2 $\times$ , or 3 $\times$ interpolation, three additional  $2\times$  half-band interpolation filters, a final 2× NRZ mode interpolator filter, FIR85, that can be bypassed, and a quadrature modulator that consists of a 48-bit NCO and an inverse sinc block.

All of the interpolation filters accept in-phase (I) and quadrature (Q) data streams as a complex data stream. Similarly, the quadrature modulator and inverse sinc function also accept input data as a complex data stream. Thus, any use of the digital datapath functions requires the input data to be a complex data stream.

In bypass mode ( $1\times$  interpolation), the input data stream is expected to be real data.



## <span id="page-49-1"></span>**Table 32. Pipeline Delay (Latency) for Various DAC Blocks**

<sup>1</sup> The pipeline delay given is a representative number, and may vary by a cycle or two based on the internal handoff timing conditions at startup.

The pipeline delay changes based on the digital datapath functions that are selected. See [Table 32](#page-49-1) for examples of the pipeline delay per block. These delays are in addition to the JESD204B latency.

# **DATA FORMAT**

The input data format for all modes on th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is 16-bit, twos complement. The digital datapath and the DAC decoder operate in twos complement format.

To avoid the NCO frequency leakage, the digital codes fed into the DAC must be balanced around zero code (number of positive codes must be equal to the number of negative codes). That is, input DC offset must be removed from the input digital code. If not, the leakage can become apparent when using the NCO to shift a signal that is above or below 0 Hz when synthesized. The NCO frequency is seen as a small spur at the NCO FTW.

# **INTERPOLATION FILTERS**

The main digital path contains five half-band interpolation filters, plus a final half-band interpolation filter that is used in 2× NRZ mode. The filters are cascaded as shown i[n Figure 107.](#page-49-0) 

The first pair of filters is a  $2 \times$  (HB2) or  $3 \times$  (HB3) filter. Each of these filters has two options for bandwidth, 80% or 90%. The 80% filters are lower power than the 90%. The filters default to the lower power 80% bandwidth. To select the filter bandwidth as 90%, program the FILT\_BW bit in the DATAPATH\_CFG register to 1 (Register 0x111, Bit  $4 = 0b1$ ).

Following the first pair of filters is a series of  $2\times$  half-band filters, each of which halves the usable bandwidth of the previous one. HB4 has 45%, HB5 has 22.5%, and HB6 has 11.25% of the f<sub>DATA</sub> bandwidth.

The final half-band filter, FIR85, is used in the 2× NRZ mode. It is clocked at the  $2 \times f_{\text{DAC}}$  rate and has a usable bandwidth of 45% of the f<sub>DAC</sub> rate. The FIR85 filter is a complex filter, and therefore the bandwidth is centered at 0 Hz. The FIR85 filter is used in conjunction with the complex interpolation modes to push the DAC update rate higher and move images further from the desired signal.

[Table 33](#page-50-0) shows how to select each available interpolation mode, their usable bandwidths, and their maximum data rates. Calculate the available signal bandwidth as the interpolator filter bandwidth, BWFILT, multiplied by fDAC/InterpolationFactor, as follows:

 $BW_{SIGNAL} = BW_{FILT} \times (f_{DAC}/InterpolationFactor)$ 

# **Filter Performance**

The interpolation filters interpolate between existing data in such a way that they minimize changes in the incoming data while suppressing the creation of interpolation images. This datapath is shown for each filter i[n Figure 108.](#page-50-1) 

The usable bandwidth (as shown i[n Table 33\)](#page-50-0) is defined as the frequency band over which the filters have a pass-band ripple of less than ±0.001 dB and an image rejection of greater than 85 dB. A conceptual drawing that shows the relative bandwidth of each of the filters is shown in [Figure 108.](#page-50-1) The maximum pass band amplitude of all filters is the same; they are different in the illustration to improve understanding.

# Data Sheet **AD9163**



### **Filter Performance Beyond Specified Bandwidth**

Some of the interpolation filters are specified to  $0.4 \times f_{\text{DATA}}$  (with a pass band). The filters can be used slightly beyond this ratio at the expense of increased pass-band ripple and decreased interpolation image rejection.

Figure 108. All Band Responses of Interpolation Filters

#### <span id="page-50-1"></span><span id="page-50-0"></span>**Table 33. Interpolation Modes and Usable Bandwidth**



<sup>1</sup> The data rate (f<sub>DATA</sub>) for all interpolator modes is a complex data rate, meaning each of I data and Q data run at that rate. Available signal bandwidth is the data rate multiplied by the bandwidth of the initial 2× or 3× interpolator filters, which can be set to BW = 80% or BW = 90%. This bandwidth is centered at 0 Hz.

 $2$  The 2 $\times$  NRZ filter, FIR85, can be used with any of the interpolator combinations.

<sup>3</sup> The bandwidth of the FIR85 filter is centered at 0 Hz.



<span id="page-51-0"></span>Figure 109. Interpolation Filter Performance Beyond Specified Bandwidth for the 80% Filters

[Figure 109](#page-51-0) shows the performance of the interpolation filters beyond  $0.4 \times$  f<sub>DATA</sub>. The ripple increases much slower than the image rejection decreases. This means that if the application can tolerate degraded image rejection from the interpolation filters, more bandwidth can be used.

Most of the filters are specified to  $0.45 \times f_{\text{DATA}}$  (with pass band). [Figure](#page-51-1) 110 to [Figure 117](#page-52-0) show the filter response for each of the interpolator filters on th[e AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf) 

<span id="page-51-1"></span>





<span id="page-52-0"></span>

# **DIGITAL MODULATION**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) has digital modulation features to modulate the baseband quadrature signal to the desired DAC output frequency.

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is equipped with several NCO modes. The default NCO is a 48-bit, integer NCO. The A/B ratio of the dual modulus NCO allows the output frequency to be synthesized with very fine precision. NCO mode is selected as shown in [Table 34.](#page-52-1) 

<span id="page-52-1"></span>



#### **48-Bit Dual Modulus NCO**

This modulation mode uses an NCO, a phase shifter, and a complex modulator to modulate the signal by a programmable carrier signal as shown i[n Figure 118.](#page-53-0) This configuration allows output signals to be placed anywhere in the output spectrum with very fine frequency resolution.

The NCO produces a quadrature carrier to translate the input signal to a new center frequency. A quadrature carrier is a pair of sinusoidal waveforms of the same frequency, offset 90° from each other. The frequency of the quadrature carrier is set via a FTW. The quadrature carrier is mixed with the I and Q data and then summed into the I and Q datapaths, as shown in [Figure 118.](#page-53-0) 

#### **Integer NCO Mode**

The main 48-bit NCO can be used as an integer NCO by using the following formula to create the frequency tuning word (FTW):

$$
-f_{\text{DAC}}/2 \le f_{\text{CARRIER}} < +f_{\text{DAC}}/2
$$

 $FTW = (f_{CARRIER}/f_{DAC}) \times 2^{48}$ 

where FTW is a 48-bit, twos complement number.

When in  $2 \times NRZ$  mode (FIR85 enabled with Register 0x111, Bit  $0 = 1$ ), the frequency tuning word is calculated as

```
0 \leq f_{CARRIER} < f_{DAC}FTW = (f_{CARRIER}/f_{DAC}) \times 2^{48}
```
where FTW is a 48-bit binary number.

This method of calculation causes  $f_{CARRIER}$  values in the second Nyquist zone to appear to move to  $f_{DAC} - f_{CARRIER}$  when flipping the FIR85 enable bit and not changing the FTW to account for the change in number format.

The intended effect is that a sweep of the NCO from 0 Hz to  $f_{\text{DAC}} - f_{\text{DAC}}/2^{48}$  appears seamless when the FIR85 enable bit is set to Register 0x111, Bit  $0 = 0b1$  prior to  $f_{CARRIER}/f_{DAC} = 0.5$ . As can be seen from examination, the FTWs from 0 to less than  $f_{\text{DAC}}/2$ mean the same in either case, but they mean different fCARRIER values from  $f_{DAC}/2$  to  $f_{DAC} - f_{DAC}/2^{48}$ . This effect must be considered when constructing FTW values and using the  $2\times$  NRZ mode.

The frequency tuning word is set as shown i[n Table 35.](#page-53-1) 

<span id="page-53-1"></span>



Unlike other registers, the FTW registers are not updated immediately upon writing. Instead, the FTW registers update on the rising edge of FTW\_LOAD\_REQ (Register 0x113, Bit 0). After an update request, FTW\_LOAD\_ACK (Register 0x113, Bit 1) must be high to acknowledge that the FTW has updated.

The SEL\_SIDEBAND bit (Register 0x111, Bit  $1 = 0b1$ ) is a convenience bit that can be set to use the lower sideband modulation result, which is equivalent to flipping the sign of the FTW.



#### <span id="page-53-0"></span>**Modulus NCO Mode**

The main 48-bit NCO can also be used in a dual modulus mode to create fractional frequencies beyond the 48-bit accuracy. The modulus mode is enabled by programming the MODULUS\_EN bit in the DATAPATH\_CFG register to 1 (Register 0x111, Bit 2 = 0b1).

The frequency ratio for the programmable modulus direct digital synthesis (DDS) is very similar to that of the typical accumulator-based DDS. The only difference is that N is not required to be a power of two for the programmable modulus, but can be an arbitrary integer. In practice, hardware constraints place limits on the range of values for N. As a result, the modulus extends the use of the NCO to applications that

require exact rational frequency synthesis. The underlying function of the programmable modulus technique is to alter the accumulator modulus.

Implementation of the programmable modulus function within the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is such that the fraction, M/N, is expressible per Equation 1. Note that the form of the equation implies a compound frequency tuning word with X representing the integer part and A/B representing the fractional part.

$$
\frac{f_{CARRIER}}{f_{DAC}} = \frac{M}{N} = \frac{X + \frac{A}{B}}{2^{48}}
$$
(1)

where:

X is programmed in Register 0x114 to Register 0x119. A is programmed in Register 0x12A to Register 0x12F. B is programmed in Register 0x124 to Register 0x129.

#### **Programmable Modulus Example**

Consider the case in which  $f_{\text{DAC}} = 2500 \text{ MHz}$  and the desired value of f<sub>CARRIER</sub> is 250 MHz. This scenario synthesizes an output frequency that is not a power of two submultiple of the sample rate, namely  $f_{CARRIER} = (1/10) f_{DAC}$ , which is not possible with a typical accumulator-based DDS. The frequency ratio, f<sub>CARRIER</sub>/f<sub>DAC</sub>, leads directly to M and N, which are determined by reducing the fraction (250,000,000/2,500,000,000) to its lowest terms, that is,

 $M/N = 250,000,000/2,500,000,000 = 1/10$ 

Therefore,  $M = 1$  and  $N = 10$ .

After calculation,  $X = 28147497671065$ ,  $A = 3$ , and  $B = 5$ . Programming these values into the registers for X, A, and B (X is programmed in Register 0x114 to Register 0x119, B is programmed in Register 0x124 to Register 0x129, and A is programmed in Register 0x12A to Register 0x12F) causes the NCO to produce an output frequency of exactly 250 MHz given a 2500 MHz sampling clock. For more details, refer to th[e AN-953](http://www.analog.com/an-953?doc=ad9163.pdf)  [Application Note](http://www.analog.com/an-953?doc=ad9163.pdf) on the Analog Devices, Inc., website.

#### **NCO Reset**

Resetting the NCO can be useful when determining the start time and phase of the NCO. The NCO can be reset by several different methods, including a SPI write, using the TX\_ENABLE pin, or by the SYSREF± signal. Due to internal timing variations from device to device, these methods achieve an accuracy of ±6 DAC clock cycles.

Program Register 0x800, Bits[7:6] to 0b01 to set the NCO in phase discontinuous switching mode via a write to the SPI port. Then, any time the frequency tuning word is updated, the NCO phase accumulator resets and the NCO begins counting at the new FTW.

# **Changing the NCO Frequency**

In the 48-bit NCO, the mode of updating the frequency tuning word can be changed from requiring a write to the FTW\_LOAD\_ REQ bit (Register 0x113, Bit 0) to an automatic update mode. In the automatic update mode, the FTW is updated as soon as the chosen FTW word is written.

To set the automatic FTW update mode, write the appropriate word to the FTW\_REQ\_MODE bits (Register 0x113, Bits[6:4]), choosing the particular FTW word that causes the automatic update. For example, if relatively coarse frequency steps are needed, it may be sufficient to write a single word to the MSB byte of the FTW, and therefore the FTW\_REQ\_MODE bits can be programmed to 110 (Register 0x113, Bits $[6:4] = 0b110$ ). Then, each time the most significant byte, FTW5, is written, the NCO FTW is automatically updated.

The FTW\_REQ\_MODE bits can be configured to use any of the FTW words as the automatic update trigger word. This configuration provides convenience when choosing the order in which to program the FTW registers.

The speed of the SPI port write function is guaranteed, and is a minimum of 100 MHz (see [Table 4\)](#page-5-0). Thus, the NCO FTW can be updated in as little as 240 ns with a one register write in automatic update mode.

The NCO only supports phase noncontinuous mode. In this mode, the phase accumulator is reset by updating the frequency tuning word of the NCO, making an instantaneous jump to the new frequency.

# **INVERSE SINC**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) provides a digital inverse sinc filter to compensate the DAC roll-off over frequency. The filter is enabled by setting the INVSINC\_EN bit (Register 0x111, Bit 7) and is disabled by default.

The inverse sinc (sinc<sup>-1</sup>) filter is a seven-tap FIR filter. [Figure](#page-54-0) 119 shows the frequency response of  $sin(x)/x$  roll-off, the inverse sinc filter, and the composite response. The composite response has less than ±0.05 dB pass-band ripple up to a frequency of  $0.4 \times$  f<sub>DACCLK</sub>. When 2× NRZ mode is enabled, the inverse sinc filter operates to  $0.4 \times f_{2 \times DACCLK}$ .

To provide the necessary peaking at the upper end of the pass band, the inverse sinc filter shown has an intrinsic insertion loss of about 3.8 dB.



<span id="page-54-0"></span>Figure 119. Responses of Sin(x)/x Roll-Off, the Sinc−1 Filter, and the Composite of the Two

# **DOWNSTREAM PROTECTION**

The [AD9163 h](http://www.analog.com/AD9163?doc=ad9163.pdf)as several features designed to protect the power amplifier (PA) of the system, as well as other downstream blocks. They consist of a control signal from the LMFC sync logic and a transmit enable function. The protection mechanism in each case is the blanking of data that is passed to the DAC decoder. The differences lie in the location in the datapath and slight variations of functionality.

The JESD204B serial link has several flags and quality measures to indicate the serial link is up and running error free. If any of these measures flags an issue, a signal from the LMFC sync logic is sent to a mux that stops data from flowing to the DAC decoder and replaces it with 0s.

There are several transmit enable features, including a TX\_ ENABLE register that can be used to squelch data at several points in the datapath or configure the TX\_ENABLE pin to do likewise.

# **Transmit Enable**

The transmit enable feature can be configured either as a SPI controlled function or a pin controlled function. It can be used for several different purposes. The SPI controlled function has less accurate timing due to its reliance on a microcontroller to program it; therefore, it is typically used as a preventative measure at power-up or when configuring the device.

The SPI controlled TX\_ENABLE function can be used to zero the input to the digital datapath or to zero the output from the digital datapath, as shown i[n Figure 120.](#page-56-0) If the input to the digital datapath is zeroed, any filtering that is selected filters the 0 signal, causing a gradual ramp-down of energy in the digital datapath. If the digital datapath is bypassed, as in  $1 \div$  mode, the data at the input to the DAC immediately drops to zero.

The TX\_ENABLE pin can be used for more accurate timing when enabling or disabling the DAC output. The effect of the TX\_ENABLE pin can be configured by the same TX\_ENABLE register (Register 0x03F) as is used for the SPI controlled functions, and it can be made to have the same effects as the SPI controlled function, namely to zero the input to the digital datapath or to zero the output from the digital datapath. In addition, the TX\_ENABLE pin can also be configured to ramp down (or up) the full-scale current of the DAC. The ramp down reduces the output power of the DAC by about 20 dB from full scale to the minimum output current.

The TX\_ENABLE pin can also be programmed to reset the NCO phase accumulator. Se[e Table 36](#page-55-0) for a description of the settings available for the TX\_ENABLE function.

<span id="page-55-0"></span>



<sup>1</sup> N/A means not applicable.

# **DATAPATH PRBS**

The datapath PRBS can verify th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) datapath receives and correctly decodes data. The datapath PRBS verifies the JESD204B parameters of the transmitter and receiver match, the lanes of the receiver are mapped appropriately, the lanes are appropriately inverted, and, if necessary, the start-up routine is correctly implemented.

To run the datapath PRBS test, complete the following steps:

- 1. Set up the device in the desired operating mode using the start-up sequence.
- 2. Send PRBS7 or PRBS15 data.
- 3. Write Register 0x14, Bit 2 = 0 for PRBS7 or 1 for PRBS15.
- 4. Write Register 0x14B, Bits[1:0] = 0b11 to enable and reset the PRBS test.
- 5. Write Register  $0x14B$ , Bits $[1:0] = 0b01$  to enable the PRBS test and release reset.
- 6. Wait 500 ms.
- 7. Check the status of the PRBS by checking the IRQ for the I and Q path PRBS as described in the Datapath PRBS IRQ section.
- 8. Read Register 0x14B, Bits [7:6]. Bit 6 is 0 if the I channel has any errors. Bit 7 is 0 if the Q channel has any errors.
- 9. Read Register 0x14C to read the error count for the I channel.
- 10. Read Register 0x14D to read the error count for the Q channel. The PRBS processes 32 bits at a time, and compares the 32 new bits to the previous set of 32 bits. It detects and reports only 1 error in every group of 32 bits; therefore, the error count partly depends on when the errors are seen.

For example, see the following sequence:

- Bits: 32 good, 31 good, 1 bad; 32 good [2 errors]
- Bits: 32 good, 22 good, 10 bad; 32 good [2 errors]
- Bits: 32 good, 31 good, 1 bad; 31 good, 1 bad; 32 good [3 errors]

# **DATAPATH PRBS IRQ**

The PRBS fail signals for the I and Q path are available as IRQ events. Use Register 0x020, Bits [1:0] to enable the fail signals, and then use Register 0x024, Bits [1:0] to read back the status and reset the IRQ signals. See the [Interrupt Request Operation](#page-57-0) section for more information.

<span id="page-56-0"></span>

Figure 120. Downstream Protection Block Diagram

# <span id="page-57-0"></span>INTERRUPT REQUEST OPERATION

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) provides an interrupt request output signal (IRQ) on Ball G4 that can be used to notify an external host processor of significant device events. On assertion of the interrupt, query the device to determine the precise event that occurred. The IRQ pin is an open-drain, active low output. Pull the IRQ pin high, external to the device. This pin can be tied to the interrupt pins of other devices with open-drain outputs to wire; OR these pins together.

[Figure 121](#page-57-1) shows a simplified block diagram of how the IRQ blocks work. If IRQ\_EN is low, the INTERRUPT\_SOURCE signal is set to 0. If IRQ\_EN is high, any rising edge of EVENT causes the INTERRUPT\_SOURCE signal to be set high. If any INTERRUPT\_SOURCE signal is high, the IRQ pin is pulled low. INTERRUPT\_SOURCE can be reset to 0 by either an IRQ\_RESET signal or a DEVICE\_RESET signal.

Depending on the STATUS\_MODE signal, the EVENT\_STATUS bit reads back an event signal or INTERRUPT\_SOURCE signal. The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) has several interrupt register blocks (IRQ) that can monitor up to 75 events (depending on device configuration). Certain details vary by IRQ register block as described i[n Table 37.](#page-57-2) [Table 38 s](#page-57-3)hows the source registers of the IRQ\_EN, IRQ\_RESET, and STATUS\_MODE signals i[n Figure 121,](#page-57-1) as well as the address where EVENT STATUS is read back.



#### <span id="page-57-2"></span>**Table 37. IRQ Register Block Details**

# **INTERRUPT SERVICE ROUTINE**

Interrupt request management starts by selecting the set of event flags that require host intervention or monitoring. Enable the events that require host action so that the host is notified when they occur. For events requiring host intervention upon IRQ activation, run the following routine to clear an interrupt request:

- 1. Read the status of the event flag bits that are being monitored.
- 2. Disable the interrupt by writing 0 to IRQ\_EN.
- 3. Read the event source.
- 4. Perform any actions that may be required to clear the cause of the event. In many cases, no specific actions may be required.
- 5. Verify that the event source is functioning as expected.
- 6. Clear the interrupt by writing 1 to IRQ\_RESET.
- 7. Enable the interrupt by writing 1 to IRQ\_EN.



Figure 121. Simplified Schematic of IRQ Circuitry

#### <span id="page-57-3"></span><span id="page-57-1"></span>**Table 38. IRQ Register Block Address of IRQ Signal Details**



<sup>1</sup> R is read; W is write; and R/W is read/write.

<sup>2</sup> N/A means not applicable.

# <span id="page-58-0"></span>APPLICATIONS INFORMATION **HARDWARE CONSIDERATIONS**

### **Power Supply Recommendations**

All the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) supply domains must remain as noise free as possible for the best operation. Power supply noise has a frequency component that affects performance, and is specified in volts rms terms.

An LC filter on the output of the power supply is recommended to attenuate the noise, and must be placed as close to th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) as possible. The VDD12\_CLK supply is the most noise sensitive supply on the device, followed by the VDD25\_DAC and VNEG\_N1P2 supplies, which are the DAC output rails. It is highly recommended that the VDD12\_CLK be supplied by itself with an ultralow noise regulator such as the [ADM7154](http://www.analog.com/adm7154?doc=ad9163.pdf) or [ADP1761](http://www.analog.com/adp1761?doc=AD9163.pdf) to achieve the best phase noise performance possible. Noisier regulators impose phase noise onto the DAC output.

The VDD12A supply can be connected to the digital DVDD supply with a separate filter network. All of the SERDES 1.2 V supplies can be connected to one regulator with separate filter networks. The IOVDD supply can be connected to the VDD25\_ DAC supply with a separate filter network, or can be powered from a system controller (for example, a microcontroller), 1.8 V to 3.3 V supply. The power supply sequencing requirement must be met; therefore, a switch or other solution must be used when connected to the IOVDD supply with VDD25\_DAC.

<span id="page-58-2"></span><span id="page-58-1"></span>Take note of the maximum power consumption numbers given i[n Table 3 t](#page-4-0)o ensure the power supply design can tolerate temperature and IC process variation extremes. The amount of current drawn is dependent on the chosen use cases, and specifications are provided for several use cases to illustrate examples and contributions from individual blocks, and to assist in calculating the maximum required current per supply.

Another consideration for the power supply design is peak current handling capability. Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) draws more current in the main digital supply when synthesizing a signal with significant amplitude variations, such as a modulated signal, as compared to when in idle mode or synthesizing a dc signal. Therefore, the power supply must be able to supply current quickly to accommodate burst signals such as GSM, TDMA, or other signals that have an on/off time domain response. Because the amount of current variation depends on the signals used, it is best to perform lab testing first to establish ranges. A typical difference can be several hundred milliamperes.

# **Power Sequencing**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) requires power sequencing to avoid damage to the DAC. A board design with the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) must include a power sequencer chip, such as th[e ADM1184,](http://www.analog.com/adm1184?doc=ad9163.pdf) to ensure that the domains power up in the correct order. The [ADM1184](http://www.analog.com/adm1184?doc=ad9163.pdf) monitors the level of power domains upon power-up. It sends an enable signal to the next grouping of power domains. When all power domains are powered up, a power-good signal is sent to the system controller to indicate all power supplies are powered up.

The IOVDD, VDD12A, VDD12\_CLK, and DVDD domains must be powered up first. Then, the VNEG\_N1P2, VDD\_1P2, PLL\_CLK\_VDD12, DVDD\_1P2, and SYNC\_VDD\_3P3 can be powered up. The VDD25\_DAC domain must be powered up last. There is no requirement for a power-down sequence.

### **Power and Ground Planes**

Solid ground planes are recommended to avoid ground loops and to provide a solid, uninterrupted ground reference for the high speed transmission lines that require controlled impedances. It is recommended that power planes be stacked between ground layers for high frequency filtering. Doing so adds extra filtering and isolation between power supply domains in addition to the decoupling capacitors.

Do not use segmented power planes as a reference for controlled impedances unless the entire length of the controlled impedance trace traverses across only a single segmented plane. These and additional guidelines for the topology of high speed transmission lines are described in th[e JESD204B Serial Interface Inputs](#page-58-3)  [\(SERDIN0± to SERDIN7±\)](#page-58-3) section.

For some applications, where highest performance and higher output frequencies are required, the choice of PCB materials significantly impacts results. For example, materials such as polyimide or materials from the Rogers Corporation can be used, for example, to improve tolerance to high temperatures and improve performance. Rogers 4350 material is used for the top three layers in some of the evaluation board designs: between the top signal layer and the ground layer below it, between the ground layer and an internal signal layer, and between that signal layer and another ground layer.

#### <span id="page-58-3"></span>**JESD204B Serial Interface Inputs (SERDIN0± to SERDIN7±)**

When considering the layout of the JESD204B serial interface transmission lines, there are many factors to consider to maintain optimal link performance. Among these factors are insertion loss, return loss, signal skew, and the topology of the differential traces.

# AD9163 Data Sheet

#### <span id="page-59-1"></span>**Insertion Loss**

The JESD204B specification limits the amount of insertion loss allowed in the transmission channel (se[e Figure 93\)](#page-33-0). Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) equalization circuitry allows significantly more loss in the channel than is required by the JESD204B specification. It is still important that the designer of the PCB minimize the amount of insertion loss by adhering to the following guidelines:

- Keep the differential traces short by placing the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) as near the transmitting logic device as possible and routing the trace as directly as possible between the devices.
- Route the differential pairs on a single plane using a solid ground plane as a reference. It is recommended to route the SERDES lanes on the same layer as th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) to avoid vias being used in the SERDES lanes.
- Use a PCB material with a low dielectric constant  $(\leq 4)$  to minimize loss, if possible.

When choosing between the stripline and microstrip techniques, keep in mind the following considerations: stripline has less loss (see [Figure 95](#page-34-0) an[d Figure 96\)](#page-34-1) and emits less EMI, but requires the use of vias that can add complexity to the task of controlling the impedance; whereas microstrip is easier to implement (if the component placement and density allow routing on the top layer) and eases the task of controlling the impedance.

If using the top layer of the PCB is problematic or the advantages of stripline are desirable, follow these recommendations:

- Minimize the number of vias.
- If possible, use blind vias to eliminate via stub effects and use microvias to minimize via inductance.
- If using standard vias, use the maximum via length to minimize the stub size. For example, on an 8-layer board, use Layer 7 for the stripline pair (see [Figure 122\)](#page-59-0).
- For each via pair, place a pair of ground vias adjacent to them to minimize the impedance discontinuity (see [Figure 122\)](#page-59-0).



<span id="page-59-0"></span>Figure 122. Minimizing Stub Effect and Adding Ground Vias for Differential Stripline Traces

# **Return Loss**

The JESD204B specification limits the amount of return loss allowed in a converter device and a logic device, but does not specify return loss for the channel. However, every effort must be made to maintain a continuous impedance on the transmission line between the transmitting logic device and the [AD9163.](http://www.analog.com/AD9163?doc=AD9163.pdf)  Minimizing the use of vias, or eliminating them all together, reduces one of the primary sources for impedance mismatches

on a transmission line (see th[e Insertion Loss](#page-59-1) section). Maintain a solid reference beneath (for microstrip) or above and below (for stripline) the differential traces to ensure continuity in the impedance of the transmission line. If the stripline technique is used, follow the guidelines listed in th[e Insertion Loss](#page-59-1) section to minimize impedance mismatches and stub effects.

Another primary source for impedance mismatch is at either end of the transmission line, where care must be taken to match the impedance of the termination to that of the transmission line. Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) handles this internally with a calibrated termination scheme for the receiving end of the line. See the [Interface Power-Up and Input Termination](#page-31-0) section for details on this circuit and the calibration routine.

#### **Signal Skew**

There are many sources for signal skew, but the two sources to consider when laying out a PCB are interconnect skew within a single JESD204B link and skew between multiple JESD204B links. In each case, keeping the channel lengths matched to within 12.5 mm is adequate for operating the JESD204B link at speeds of up to 12.5 Gbps. This amount of channel length match is equivalent to about 85% UI on the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) evaluation board. Managing the interconnect skew within a single link is fairly straightforward. Managing multiple links across multiple devices is more complex. However, follow the 12.5 mm guideline for length matching. Th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) can handle more skew than the 85% UI due to the 6 PCLK buffer in the JESD204B receiver, but matching the channel lengths as close as possible is still recommended.

#### **Topology**

Structure the differential SERDINx $\pm$  pairs to achieve 50  $\Omega$  to ground for each half of the pair. Stripline vs. microstrip tradeoffs are described in th[e Insertion Loss](#page-59-1) section. In either case, it is important to keep these transmission lines separated from potential noise sources such as high speed digital signals and noisy supplies. If using stripline differential traces, route them using a coplanar method, with both traces on the same layer. Although this method does not offer more noise immunity than the broadside routing method (traces routed on adjacent layers), it is easier to route and manufacture so that the impedance continuity is maintained. An illustration of broadside vs. coplanar is shown i[n Figure 123.](#page-59-2) 



<span id="page-59-2"></span>Figure 123. Broadside vs. Coplanar Differential Stripline Routing Techniques

# Data Sheet **AD9163**

When considering the trace width vs. copper weight and thickness, the speed of the interface must be considered. At multigigabit speeds, the skin effect of the conducting material confines the current flow to the surface. Maximize the surface area of the conductor by making the trace width made wider to reduce the losses. Additionally, loosely couple differential traces to accommodate the wider trace widths. This coupling helps reduce the crosstalk and minimize the impedance mismatch when the traces must separate to accommodate components, vias, connectors, or other routing obstacles. Tightly coupled vs. loosely coupled differential traces are shown in [Figure 124.](#page-60-0)



<span id="page-60-0"></span>Figure 124. Tightly Coupled vs. Loosely Coupled Differential Traces

### **AC Coupling Capacitors**

The [AD9163](http://www.analog.com/AD9163?doc=AD9163.pdf) requires that the JESD204B input signals be ac-coupled to the source. These capacitors must be 100 nF and placed as close as possible to the transmitting logic device.

To minimize the impedance mismatch at the pads, select the package size of the capacitor so that the pad size on the PCB matches the trace width as closely as possible.

# **SYNCOUT±, SYSREF±, and CLK± Signals**

The  $\overline{\text{SYNCOUNT}+}$  and SYSREF $\pm$  signals on th[e AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is low speed LVDS differential signals. Use controlled impedance traces routed with 100 Ω differential impedance and 50 Ω to ground when routing these signals. As with the SERDIN0± to SERDIN7± data pairs, it is important to keep these signals separated from potential noise sources such as high speed digital signals and noisy supplies.

Separate the  $\overline{\text{SYNCOUT}\pm}$  signal from other noisy signals, because noise on the  $\overline{\text{SYNCOUT}\pm}$  may be interpreted as a request for /K/ characters.

It is important to keep similar trace lengths for the CLK± and SYSREF± signals from the clock source to each of the devices on either end of the JESD204B links (se[e Figure 125\)](#page-60-1). If using a clock chip that can tightly control the phase of CLK± and SYSREF±, the trace length matching requirements are greatly reduced.



<span id="page-60-1"></span>Figure 125. SYSREF± Signal and Device Clock Trace Length

# ANALOG INTERFACE CONSIDERATIONS **ANALOG MODES OF OPERATION**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) uses the quad-switch architecture shown i[n Figure 126.](#page-61-0)  Only one pair of switches is enabled during a half-clock cycle, thus requiring each pair to be clocked on alternative clock edges. A key benefit of the quad-switch architecture is that it masks the code dependent glitches that occur in the conventional two-switch DAC architecture.



Figure 126. Quad-Switch Architecture

<span id="page-61-0"></span>In two-switch architecture, when a switch transition occurs and  $D_1$  and  $D_2$  are in different states, a glitch occurs. However, if  $D_1$ and  $D_2$  happen to be at the same state, the switch transitions and no glitches occur. This code dependent glitching causes an increased amount of distortion in the DAC. In quad-switch architecture (no matter what the codes are), two switches are always transitioning at each half-clock cycle, thus eliminating the code-dependent glitches, but, in the process, creating a constant glitch at  $2 \times f_{\text{DAC}}$ . For this reason, a significant clock spur at  $2 \times$ f<sub>DAC</sub> is evident in the DAC output spectrum.



Figure 127. Two-Switch and Quad-Switch DAC Waveforms

As a consequence of the quad-switch architecture enabling updates on each half-clock cycle, it is possible to operate that DAC core at  $2\times$  the DAC clock rate if new data samples are latched into the DAC core on both the rising and falling edges of the DAC clock. This notion serves as the basis when operating the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) in either Mix-Mode or return to zero (RZ) mode. In each case, the DAC core is presented with new data samples on each clock edge: in RZ mode, the rising edge clocks data and the falling edge clocks zero, whereas in Mix-Mode, the falling edge sample is simply the complement of the rising edge sample value.

When Mix-Mode is used, the output is effectively chopped at the DAC sample rate. This chopping has the effect of reducing the power of the fundamental signal while increasing the power of the images centered around the DAC sample rate, thus improving the dynamic range of these images.



This ability to change modes provides the user the flexibility to place a carrier anywhere in the first three Nyquist zones, depending on the operating mode selected. Switching between baseband and Mix-Mode reshapes the sinc roll-off inherent at the DAC output. In baseband mode, the sinc null appears at f<sub>DAC</sub> because the same sample latched on the rising clock edge is also latched again on the falling clock edge, thus resulting in the same ubiquitous sinc response of a traditional DAC. In Mix-Mode, the complement sample of the rising edge is latched on the falling edge, therefore pushing the sinc null to  $2 \times f_{\text{DAC}}$ . [Figure 129](#page-61-1) shows the ideal frequency response of the three modes with the sinc roll-off included.



Figure 129. Sinc Roll-Off for NRZ, RZ, and Mix-Mode Operation

<span id="page-61-1"></span>The quad-switch can be configured via the SPI (Register 0x152, Bits[1:0]) to operate in either NRZ mode (0b00), RZ mode (0b10), or Mix-Mode (0b01). The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) has an additional frequency response characteristic due to the FIR85 filter. This filter samples data on both the rising and falling edges of the DAC clock, in essence doubling the input clock frequency. As a result, the NRZ (normal) mode roll-off i[n Figure 129](#page-61-1) is extended to  $2 \times f_{\text{DAC}}$  i[n Figure 129,](#page-61-1) and follows the Mix-Mode roll-off due to the zero-order hold at  $2 \times$  DAC clock (se[e Figure 130\)](#page-62-0).



### <span id="page-62-0"></span>**CLOCK INPUT**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) contains a low jitter, differential clock receiver that is capable of interfacing directly to a differential or single-ended clock source. Because the input is self biased with a nominal impedance of 90 Ω, it is recommended that the clock source be ac-coupled to the CLK± input pins. The nominal differential input is 1 V p-p, but the clock receiver can operate with a span that ranges from 250 mV p-p to 2.0 V p-p. Better phase noise performance is achieved with a higher clock input level.



The quality of the clock source, as well as its interface to the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) clock input, directly impacts ac performance. Select the phase noise and spur characteristics of the clock source to meet the target application requirements. Phase noise and spurs at a given frequency offset on the clock source are directly translated to the output signal. It can be shown that the phase noise characteristics of a reconstructed output sine wave are related to the clock source by  $20 \times log_{10}$  (four/fclx) when the DAC clock path contribution is negligible.

[Figure 133](#page-63-0) shows a clock source based on th[e ADF4355](http://www.analog.com/ADF4355?doc=ad9163.pdf) low phase noise/jitter PLL. Th[e ADF4355](http://www.analog.com/ADF4355?doc=ad9163.pdf) can provide output frequencies from 54 MHz up to 6.8 GHz.

The clock control registers exist at Address 0x082 through Address 0x084. CLK\_DUTY (Register 0x082) can be used to enable duty cycle correction (Bit 7), enable duty cycle offset control (Bit 6), and set the duty cycle offset (Bits[4:0]). The duty cycle offset word is a signed magnitude word, with Bit 4 being

the sign bit (1 is negative) and Bits[3:0] the magnitude. The duty cycle adjusts across a range of approximately ±3%. Recommended settings for this register are listed in th[e Start-Up Sequence s](#page-66-0)ection.

The clock input has a register that adjusts the phase of the CLK+ and CLK− inputs. This register is located at Address 0x07F. The register has a signed magnitude (1 is negative) value that adds capacitance at ~20 fF per step to either the CLK+ or the CLK− input, according to [Table 39.](#page-62-1) The CLK\_PHASE\_TUNE register can be used to adjust the clock input phase for better DAC image rejection.



#### <span id="page-62-1"></span>**Table 39. CLK± Phase Adjust Values**

The improvement in performance from making these adjustments depends on the accuracy of the balance of the clock input balun and varies from unit to unit. Thus, if a high level of image rejection is required, it is likely that a per unit calibration is necessary. Performing this calibration can yield significant improvements, as much as 20 dB additional rejection of the image due to imbalance. [Figure 132](#page-62-2) shows the results of tuning clock phase, duty cycle (left at default in this case), and cross control. The improvement to performance, particularly at higher frequencies, can be as much as 20 dB.



<span id="page-62-2"></span>Figure 132. Performance Improvement from Tuning the Clock Input



Figure 133. Possible Signal Chain for CLK± Input

# <span id="page-63-0"></span>**SHUFFLE MODE**

The spurious performance of the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) can be improved with a feature called shuffle mode. Shuffle mode uses proprietary technology to spread the energy of spurious signals across the DAC output as random noise. Shuffle mode is enabled by programming Register 0x151, Bit 2 = 0b1. Because shuffle is implemented with the MSBs, it is more effective when the DAC is operated with a small amount of digital backoff.

The amount of noise rise caused by shuffle mode is directly related to the power in the affected spurious signals. Because the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) has good spurious performance without shuffle active, the penalty of shuffle mode to the noise spectral density is typically about 1 dB to 3 dB. Shuffle mode reduces spurious performance related to clock and foldback spurs, but does not affect real harmonics of the DAC output. Examples of the effects of shuffle mode are given in the [Typical Performance](#page-12-0)  [Characteristics](#page-12-0) section (se[e Figure 47,](#page-19-0) [Figure 48,](#page-19-1) [Figure 62,](#page-21-0)  [Figure 63,](#page-21-1) an[d Figure 64\)](#page-21-2).

# **DLL**

The CLK $\pm$  input goes to a high frequency DLL to ensure robust locking of the DAC sample clock to the input clock. The DLL is configured and enabled as part of the recommended start-up sequence. The DLL control registers are located at Register 0x090 through Register 0x09B. The DLL settings are determined during product characterization and are given in the recommended start-up sequence (see th[e Start-Up Sequence s](#page-66-0)ection). It is not normally necessary to change these values, nor is the product characterization data valid on any settings other than the recommended ones.

# **VOLTAGE REFERENCE**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) output current is set by a combination of digital control bits and the ISET reference current, as shown i[n Figure 134.](#page-63-1) 



Figure 134. Voltage Reference Circuit

<span id="page-63-1"></span>The reference current is obtained by forcing the band gap voltage across an external 9.6 kΩ resistor from ISET (Ball A12) to VNEG\_N1P2. The 1.2 V nominal band gap voltage (VREF) generates a 125 μA reference current, ISET, in the 9.6 kΩ resistor, RSET. The maximum full-scale current setting is related to the external resistor by the following equation:

 $I_{\text{OUTFS}} = 1.2 \text{ V}/R_{\text{SET}} \text{ (k}\Omega) \times 320 \text{ (mA)}$ 

Note the following constraints when configuring the voltage reference circuit:

- Both the 9.6 kΩ resistor and 1  $\mu$ F bypass capacitor are required for proper operation.
- Adjusting the DAC output full-scale current, IouTFS, from its default setting of 40 mA must be performed digitally.
- The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is not a multiplying DAC. Modulation of the reference current, ISET, with an ac signal is not supported.
- The band gap voltage appearing at the VREF pin must be buffered for use with an external circuitry because it has a high output impedance.
- An external reference can be used to overdrive the internal reference by connecting it to the VREF pin.

The I<sub>OUTFS</sub> value can be adjusted digitally over an 8 mA to 40 mA range by the ANA\_FULL\_SCALE\_CURRENT[9:0] bits (Register 0x042, Bits[7:0] and Register 0x041, Bits[1:0]). The following equation relates I<sub>OUTFS</sub> to the ANA\_FULL\_SCALE\_ CURRENT[9:0] bits, which can be set from 0 to 1023.

 $I_{\text{OUTFS}} = 32 \text{ mA} \times (ANA$  FULL\_SCALE\_CURRENT[9:0]/1023) + 8 mA

Note that the default value of 0x3FF generates 40 mA full scale, and this value is used for most of the characterization presented in this data sheet, unless noted otherwise.

# **TEMPERATURE SENSOR**

The [AD9163 h](http://www.analog.com/AD9163?doc=ad9163.pdf)as a band gap temperature sensor for monitoring the temperature changes of the [AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf) The temperature must be calibrated against a known temperature to remove the device to device variation on the band gap circuit that senses the temperature.

To calibrate the temperature, the user must take a reading at a known ambient temperature for a single point calibration of the [AD9163 d](http://www.analog.com/AD9163?doc=ad9163.pdf)evice. The slope for the formula is then calculated as

 $M = (T_{REF} + 190) / ((CODE\_REF) / 1000)$ 

where:

 $T_{REF}$  is the calibrated temperature at which the temperature sensor is read.

CODE\_REF is the readback code at the measured temperature, TREF.

To monitor temperature change,

 $T_X = T_{REF} + M \times (CODE\_X - CODE\_REF)/1000$ 

where:

CODE X is the readback code at the unknown temperature,  $T_X$ . CODE REF is the readback code at the calibrated temperature,  $T_{REF.}$ 

To use the temperature sensor, enable it by setting Register 0x135 to Register 0xA1. The user must write a 1 to Register 0x134, Bit 0 before reading back the die temperature from Register 0x132 (LSB) and Register 0x133 (MSB).

# **ANALOG OUTPUTS**

#### **Equivalent DAC Output and Transfer Function**

Th[e AD9163 p](http://www.analog.com/AD9163?doc=ad9163.pdf)rovides complementary current outputs, OUTPUT+ and OUTPUT−, that sink current from an external load that is referenced to the 2.5 V VDD25\_DAC supply[. Figure 135 s](#page-64-0)hows an equivalent output circuit for the DAC. Compared to most current output DACs of this type, the outputs of the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) consists of a constant current (IFIXED), and a peak differential ac current,  $I_{CS}$  ( $I_{CS}$  =  $I_{CSP}$  +  $I_{CSN}$ ). These two currents combine to form the  $I_{INTx}$  currents shown in [Figure 135.](#page-64-0) The internal currents, I<sub>INTP</sub> and I<sub>INTN</sub>, are sent to the output pin and to an input termination resistance equivalent to 100  $Ω$  pulled to the VDD25\_DAC supply  $(R_{INT})$ . This termination serves to divide the output current based on the external termination resistors that are pulled to VDD25\_DAC.



*Figure 135. Equivalent DAC Output Circuit* 

<span id="page-64-0"></span>The example shown i[n Figure 135](#page-64-0) can be modeled as a pair of dc current sources that source a current of IouTFS to each output.

This differential ac current source is used to model the signal (that is, a digital code) dependent nature of the DAC output. The polarity and signal dependency of this ac current source are related to the digital code (F) by the following equation:

$$
F(code) = (DACCODE - 32,768)/32,768
$$
 (2)

where:

 $-1 \leq F (code) < +1.$  $DACCODE = 0$  to 65,535 (decimal).

The current that is measured at the OUTPUT+ and OUTPUT− outputs is as follows:

$$
OUTPUT + = (I_{FXED} (mA) + (F \times I_{OUTFS}) / F_{MAX} (mA)) \times (R_{INT} / (R_{INT} + R_{LOAD}))
$$
\n(3)

$$
OUTPUT-=(I_{FKED}(mA)+((F_{MAX}-F)\times I_{OUTFS})/F_{MAX}(mA))\times \\ (R_{INT}/(R_{INT}+R_{LOAD}))
$$

The IFIXED value is about 3.8 mA. It is important to note that the [AD9163 o](http://www.analog.com/AD9163?doc=ad9163.pdf)utput cannot support dc coupling to the external load, and thus must be ac-coupled through appropriately sized capacitors for the chosen operating frequencies[. Figure 136](#page-64-1) shows the OUTPUT+ vs. DAC code transfer function when  $I<sub>OUTFS</sub>$  is set to  $40 \text{ m}$  $\text{A}$ 



#### <span id="page-64-1"></span>**Peak DAC Output Power Capability**

The maximum peak power capability of a differential current output DAC is dependent on its peak differential ac current, IPEAK, and the equivalent load resistance it sees. In the case of a 1:1 balun with 100 Ω differential source termination, the equivalent load that is seen by the DAC ac current source is 50  $\Omega$ . If the  $AD9163$  is programmed for an  $I_{\text{OUTFS}} = 40 \text{ mA}$ , its ideal peak ac current is 20 mA and its maximum power, delivered to the equivalent load, is  $10 \times (R_{INT}/(R_{INT} + R_{LOAD})) = 8$  mW, that is, P = I <sup>2</sup>R. Because the source and load resistance seen by the 1:1 balun are equal, this power is shared equally. Therefore, the output load receives 4 mW, or 6 dB maximum power.

To calculate the rms power delivered to the load, consider

- Peak to rms ratio of the digital waveform
- Any digital backoff from digital full scale

- DAC sinc response and nonideal losses in the external network
- DAC analog roll-off due to switch parasitic capacitance and load impedance

For example, a sine wave with no digital backoff ideally measures 6 dBm. If a typical balun loss of 1.2 dB is included, expect to measure 4.8 dBm of actual power in the region where the sinc response of the DAC has negligible influence and analog roll-off has not begun. Increasing the output power is best accomplished by increasing I<sub>OUTFS</sub>. An example of DAC output characteristics for several balun and board types is shown i[n Figure 137.](#page-65-0) 



Figure 137. Measured DAC Output Response;  $f_{DAC} = 6$  GSPS

14415-123

#### <span id="page-65-0"></span>**Output Stage Configuration**

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is intended to serve high dynamic range applications that require wide signal reconstruction bandwidth (such as a DOCSIS cable modem termination system (CMTS)) and/or high IF/RF signal generation. Optimum ac performance can be realized only when the DAC output is configured for differential (that is, balanced) operation with its output common-mode voltage biased to a stable, low noise 2.5 V nominal analog supply (VDD25\_DAC).

The output network used to interface to the DAC provides a near 0  $\Omega$  dc bias path to VDD25\_DAC. Any imbalance in the output impedance over frequency between the OUTPUT+ and OUTPUT− pins degrades the distortion performance (mostly even order) and noise performance. Component selection and layout are critical in realizing the performance potential of the [AD9163.](http://www.analog.com/AD9163?doc=ad9163.pdf) 

Most applications that require balanced to unbalanced conversion from 10 MHz to 3 GHz can take advantage of several available transformers that offer impedance ratios of both 2:1 and 1:1.

[Figure 138](#page-65-1) shows the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) interfacing to the Mini-Circuits TCM1-63AX+ and the TC1-1-43X+ transformers.



<span id="page-65-1"></span>Figure 138. Recommended Transformer for Wideband Applications with Upper Bandwidths of up to 5 GHz

To assist in matching the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) output, an equivalent model of the output was developed, and is shown in [Figure](#page-65-2) 139. This equivalent model includes all effects from the ideal 40 mA current source in the die to the ball of the CSP\_ BGA package, including parasitic capacitance, trace inductance and resistance, contact resistance of solder bumps, via inductance, and other effects.



Figure 139. Equivalent Circuit Model of the DAC Output

<span id="page-65-2"></span>A Smith chart is provided i[n Figure 140](#page-65-3) showing the simulated S11 of the DAC output, using the model i[n Figure](#page-65-2) 139. The plot was taken using the circuit in [Figure](#page-65-2) 139, with a 100  $\Omega$  differential load instead of the balun. For the measured response of the DAC output, se[e Figure 137.](#page-65-0) 





**IMPEDANCE = Z0 × (0.125 + j0.100)** 14415-125

<span id="page-65-3"></span>Figure 140. Simulated Smith Chart Showing the DAC Output Impedance,  $Z_0 = 100 \Omega$ 

**m2**

**FREQUENCY = 100MH** 

**m3 FREQUENCY = 1GHz**

**S (1, 1) = 0.367/–144.722 IMPEDANCE = Z0 × (0.499 – j0.245)**

# <span id="page-66-0"></span>START-UP SEQUENCE

A number of steps is required to program the [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) to the proper operating state after the device is powered up. This sequence is divided into several steps, and is listed in [Table 40,](#page-66-3) [Table 41,](#page-66-4) an[d Table 42,](#page-67-0) along with an explanation of the purpose of each step. Private registers are reserved but must be written for proper operation. Blank cells i[n Table 40](#page-66-3) to [Table 42](#page-67-0) mean that the value depends on the result as described in the description column.

The [AD9163](http://www.analog.com/AD9163?doc=ad9163.pdf) is calibrated at the factory as part of the automatic test program. The configure DAC start-up sequence loads the factory calibration coefficients, as well as configures some

parameters that optimize the performance of the DAC and the DAC clock DLL (see [Table 40\)](#page-66-3). Run this sequence whenever the DAC is powered down or reset.

The configure JESD204B sequence configures the SERDES block and then brings up the links (se[e Table 41\)](#page-66-4). First, run the configure DAC start-up sequence, then run the configure JESD204B sequence.

Follow the configure NCO sequence if using the NCO (see [Table 42\)](#page-67-0). The configure DAC start-up sequence is run first, then the configure NCO sequence.



<span id="page-66-3"></span>**Table 40. Configure DAC Start-Up Sequence After Power-Up** 

<sup>1</sup> N/A means not applicable.

<span id="page-66-4"></span>

<span id="page-66-2"></span><span id="page-66-1"></span>



# <span id="page-67-0"></span>**Table 42. Configure NCO Sequence**



# <span id="page-68-0"></span>REGISTER SUMMARY

### **Table 43. Register Summary**





# Data Sheet **AD9163**










### REGISTER DETAILS

### **Table 44. Register Details**









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Ĭ.

j.




























































































### OUTLINE DIMENSIONS



(BC-169-2)

### Dimensions shown in millimeters

### **ORDERING GUIDE**



 $1 Z =$  RoHS Compliant Part.



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